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GEL LAYERS FOR LIGHT EMITTING DIODES AND METHODS OF FABRICATING SAME

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application claims priority to U.S. Patent Application No. 13/369,996, filed February 9, 2012, entitled *Gel Underfill Layers for Light Emitting Diodes and Methods of Fabricating Same*, which itself is a continuation-in-part of and claims priority to U.S. Patent Application No. 13/160,793, filed June 15, 2011, entitled *Conformal Gel Layers for Light Emitting Diodes and Methods of Fabricating Same*, assigned to the assignee of the present application, the disclosures of both of which are hereby incorporated herein by reference as if set forth in their entirety herein.

BACKGROUND OF THE INVENTION

[0002] This invention relates to light emitting devices and assemblies and methods of manufacturing the same, and more particularly, to Light Emitting Diodes (LEDs) and assemblies thereof.

[0003] LEDs are widely known solid-state lighting elements that are capable of generating light upon application of voltage thereto. LEDs generally include a diode region having first and second opposing faces, and include therein an n-type layer, a p-type layer and a p-n junction. An anode contact ohmically contacts the p-type layer and a cathode contact ohmically contacts the n-type layer. The diode region may be epitaxially formed on a substrate, such as a sapphire, silicon, silicon carbide, gallium arsenide, gallium nitride, etc., growth substrate, but the completed device may not include a substrate. The diode region may be fabricated, for example, from silicon carbide, gallium nitride, gallium phosphide, aluminum nitride and/or gallium arsenide-based materials and/or from organic semiconductor-based materials. Finally, the light radiated by the LED may be in the visible or ultraviolet (UV) regions, and the LED may incorporate wavelength conversion material such as phosphor.

[0004] LEDs are increasingly being used in lighting/illumination applications, with a goal being to provide a replacement for the ubiquitous incandescent light bulb.

SUMMARY OF THE INVENTION

[0005] Light emitting devices according to various embodiments described herein include a light emitting diode die on a mounting substrate and a conformal gel layer on the mounting substrate and/or on the light emitting diode die. As used herein, a "conformal" layer includes opposing surfaces that both conform to a contour of the underlying element on which the conformal layer extends. Moreover, as used herein, a "gel" means a colloid in which a disperse phase has combined with a dispersion medium to produce a semi-solid material, such as a jelly.

[0006] Conformal gel layers may be used with light emitting diode dies and mounting substrates to form light emitting devices according to various embodiments described herein. For example, in some embodiments, a light emitting device includes a mounting substrate and a light emitting diode die adjacent the mounting substrate, to define a gap therebetween. A conformal gel layer is provided on the mounting substrates that extends at least partially into the gap. The conformal gel layer may also extend from the gap onto the light emitting die, so that the opposing surfaces of the conformal layer may conform to the contour of the mounting substrate and/or the contour of the light emitting diode die. The gap may be defined by a bond region that connects the light emitting diode die to the mounting substrate, and that is recessed from an edge of the light emitting diode die. In some embodiments, the conformal gel layer may fill the gap.

[0007] The light emitting devices that include a conformal gel layer may also include a conformal or non-conformal phosphor layer on the conformal gel layer. As used herein, the term "phosphor" includes any wavelength conversion materials that are sometimes called luminescent, fluorescent and/or phosphorescent. When a conformal phosphor layer is used, the conformal phosphor layer may extend onto the mounting substrate and/or onto the light emitting diode die, and may include opposing surfaces that both conform to a contour of the mounting substrate and/or the light emitting diode die. A lens may be provided on the conformal phosphor layer. In other embodiments, a non-conformal phosphor layer is used, and a lens may be provided on the non-conformal phosphor layer. In yet other embodiments, a phosphor layer need not be included on the conformal gel layer. Thus, a lens may be provided on the conformal gel layer without providing a conformal or non-conformal phosphor layer.

[0008] In some embodiments, the conformal gel layer and the phosphor layer may both comprise silicone. However, the phosphor layer is not a gel. In some embodiments, the conformal gel layer may be at least five times thinner than the phosphor layer. The gel layer

may have a modulus that is less than the phosphor layer, in some embodiments, and that is at least one, two or three orders of magnitude less than the phosphor layer in other embodiments.

[0009] Other embodiments described herein can provide a light emitting device that comprises a mounting substrate and a light emitting diode die on the mounting substrate, wherein a conformal gel layer is provided on the mounting substrate and extends at least partially onto the light emitting diode die. A conformal or non-conformal phosphor layer may be provided on the conformal gel layer in some embodiments, and a lens may be provided on the phosphor layer. In other embodiments, a lens, which may include encapsulation material therein, is provided on the conformal gel layer, without providing an intervening phosphor layer.

[0010] Yet other embodiments described herein can provide a light emitting device that comprises a light emitting diode die and a gel layer that is less than about 20 μ m thick on the light emitting diode die. In other embodiments, the gel layer may be less than about 10 μ m thick and, in still other embodiments, is about 5 μ m or about 3 μ m thick. The gel layer may be a conformal gel layer. A phosphor layer may be provided on the gel layer.

[0011] Still other embodiments described herein can provide a light emitting device that comprises a light emitting diode die, a gel layer on the light emitting diode die and a phosphor layer on the gel layer. The gel layer and the phosphor layer may both comprise silicone, but the phosphor layer is not a gel. The gel layer may be at least five times thinner than the phosphor layer. The gel layer may have a modulus that is less than the phosphor layer, in some embodiments, and that is at least one, two or three orders of magnitude less than the phosphor layer in other embodiments.

[0012] Conformal gel layers according to some embodiments described herein may provide embodiments of a filler that is provided in a gap that is defined by a recessed bond region that connects a light emitting diode die to a mounting substrate, wherein the light emitting device also includes a phosphor layer that extends from the mounting substrate across the gap and onto the light emitting diode die. The filler may be configured to prevent the phosphor layer from entering the gap sufficiently to degrade operation of the light emitting device. In some embodiments, the filler may also extend from the gap between the phosphor layer and the mounting substrate and/or from the gap between the phosphor layer and the light emitting diode die.

[0013] Light emitting devices may be fabricated according to various embodiments described herein by conformally gel coating a mounting substrate having a light

emitting diode die mounted thereon. Then, phosphor is coated and/or a lens is placed on the mounting substrate that was conformally gel coated. Gel coating may be provided by applying gel that is diluted in a solvent to the mounting substrate having the light emitting diode die mounted thereon. The gel may be applied by spraying the gel that is diluted in a solvent onto the mounting substrate, such that at least some of the solvent evaporates. In other embodiments, the gel that is diluted in the solvent is dispensed onto the mounting substrate and then at least some of the solvent is evaporated. The gel coating, the phosphor coating and the lens may all comprise silicone, but the phosphor coating and the lens are not gels.

[0014] Light emitting devices according to various embodiments described herein include a mounting substrate and an array of light emitting diode dies adjacent the mounting substrate, to define a gap between a respective light emitting diode die and the mounting substrate that is adjacent thereto. A gel layer is provided on the mounting substrate. The gel layer extends at least partially in the gaps between the light emitting diode dies and the substrate adjacent thereto, to provide an underfill. However, the gel layer does not completely cover the light emitting diode dies. In some embodiments, the gel layer does not extend on the substrate substantially beyond the array of light emitting diode dies, and also does not extend substantially on an outer face of the light emitting diode dies. As used herein, a "gel" means a colloid in which a disperse phase has combined with a dispersion medium to produce a semi-solid material, such as a jelly. Moreover, as used herein, "substantially" means that there may be some isolated islands of gel present in the given region, but the gel layer itself does not extend in the given region.

[0015] In some embodiments, an array of bond regions is provided, a respective one of which connects a respective light emitting diode die to the mounting substrate. A respective bond region is recessed from an edge of a respective light emitting diode die, to define a respective gap. Moreover, in some embodiments, the gel layer fills the gaps. Also, in some embodiments, the gel layer also extends between adjacent light emitting diode dies in the array. Finally, in other embodiments, the gel layer may also extend at least partially, and in some embodiments fully, on sidewalls of the light emitting diode dies.

[0016] Light emitting devices that include a gel underfill layer according to any embodiments described herein, may also include a conformal or nonconformal phosphor layer. As used herein, a "conformal" layer includes opposing surfaces that both conform to a contour of the underlying element on which the conformal layer extends. Moreover, as used herein, the term "phosphor" includes any wavelength conversion materials that are sometimes

called luminescent, fluorescent and/or phosphorescent. The phosphor layer is directly on the substrate, extends beyond the array of light emitting diode dies and also extends directly on the outer faces of the light emitting diode dies. In other embodiments, a lens is provided that spans the array of light emitting diode dies and extends directly on the substrate beyond the array of light emitting diode dies and directly on the outer faces of the light emitting diode dies. A conformal or nonconformal phosphor layer and a lens may also be provided according to other embodiments described herein, wherein the lens is on at least a portion of the phosphor layer.

[0017] Various embodiments described above have included an array of light emitting diode dies adjacent the mounting substrate. However, in other embodiments, a single light emitting diode die may be provided adjacent the mounting substrate to define a gap between the light emitting diode die and the mounting substrate that is adjacent thereto. A gel layer is provided on the mounting substrate. The gel layer extends at least partially in the gap between the light emitting diode die and the substrate adjacent thereto, but does not completely cover the light emitting diode die. In some embodiments, the gel does not extend on the substrate substantially beyond the light emitting diode die, and also does not extend substantially on an outer face of the light emitting diode die. In some embodiments, the gel layer fills the gap and/or extends at least partially on sidewalls of the light emitting diode die, as also described above. A phosphor layer and/or a lens may also be provided, as was described above.

[0018] Light emitting devices may be fabricated, according to various embodiments described herein, by providing a mounting substrate and an array of light emitting diode dies adjacent the mounting substrate to define a gap between a respective light emitting diode die and the mounting substrate that is adjacent thereto. A gel that is diluted in a solvent is applied on the substrate and on the array of light emitting diode dies. At least some of the solvent is then evaporated, so that the gel remains in the gaps, but does not completely cover the light emitting diode dies. In some embodiments, the gel substantially recedes from the substrate, for example from reflective areas of the substrate, beyond the array of light emitting diode dies, and also substantially recedes from an outer face of the light emitting diode dies.

[0019] The gel may be applied by dispensing at least one drop of gel that is diluted in the solvent on the substrate and on the array of light emitting diode dies, and/or by spraying the gel that is diluted in the solvent on the substrate and on the array of light emitting diode dies. Other gel-applying techniques also may be used. In some embodiments,

the gel is diluted in the solvent at a ratio of about 1:4-5 by volume. In some embodiments, the gel may fill the gaps. In other embodiments, the gel may remain in the gaps and on the substrate between adjacent light emitting diode dies, but substantially recedes from the substrate beyond the array of light emitting diode dies and also substantially recedes from an outer face of the light emitting diode dies. In yet other embodiments, the gel may remain at least partially on sidewalls of the light emitting diode dies, as well. A phosphor layer and/or a lens may then be applied or attached.

[0020] Method embodiments described above have included an array of light emitting diode dies. However, in other methods described herein, a single light emitting diode die may be provided adjacent the mounting substrate to define a gap, and a gel that is diluted in solvent is applied on the substrate and on the light emitting diode die. At least some of the solvent is evaporated so that the gel remains in the gap, but does not completely cover the light emitting diode die. In some embodiments, the gel substantially recedes from the substrate, for example from reflective areas of the substrate, beyond the light emitting diode die, and also substantially recedes from an outer face of the light emitting diode die. The gel may be applied using dispensing, spraying and/or other techniques, and the gel may fill the gap and/or remain at least partially on sidewalls of the light emitting diode die as was described above. Phosphor and/or a lens also may be applied or attached as was described above.

BRIEF DESCRIPTION OF THE DRAWINGS

[0021] Figures 1 and 2 are cross-sectional views of light emitting devices that may be used with various embodiments described herein.

[0022] Figures 3-7 are cross-sectional views of light emitting devices according to various embodiments described herein.

[0023] Figure 8 is a flowchart of methods of fabricating light emitting devices according to various embodiments described herein.

[0024] Figures 9A-9B are photographs illustrating results of reflow operations for light emitting devices that do not use a conformal gel layer according to various embodiments described herein, and Figures 9C-9D are photographs of the same light emitting devices that do use a conformal gel layer according to various embodiments described herein.

[0025] Figure 10 is a flowchart of methods of fabricating light emitting devices according to various embodiments described herein.

[0026] Figures 11-19 are cross-sectional views of light emitting devices according to various embodiments described herein, during intermediate or final fabrication according to various embodiments described herein.

[0027] Figures 20-22 are optical microscope images of light emitting devices according to various embodiments described herein.

[0028] Figures 23-25 are Scanning Electron Microscope (SEM) images of light emitting devices according to various embodiments described herein.

[0029] Figures 26-27 are Electron Diffraction Spectroscopy (EDS) spectra of light emitting devices according to various embodiments described herein.

DETAILED DESCRIPTION

[0030] The present invention now will be described more fully with reference to the accompanying drawings, in which various embodiments are shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the invention to those skilled in the art. In the drawings, the size and relative sizes of layers and regions may be exaggerated for clarity. Like numbers refer to like elements throughout.

[0031] It will be understood that when an element such as a layer, region or substrate is referred to as being "on" another element, it can be directly on the other element or intervening elements may also be present. Furthermore, relative terms such as "beneath" or "overlies" may be used herein to describe a relationship of one layer or region to another layer or region relative to a substrate or base layer as illustrated in the figures. It will be understood that these terms are intended to encompass different orientations of the device in addition to the orientation depicted in the figures. Finally, the term "directly" means that there are no intervening elements. As used herein, the term "and/or" includes any and all combinations of one or more of the associated listed items and may be abbreviated as "/".

[0032] It will be understood that, although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. These terms are only used to distinguish one element, component, region, layer or section from another region, layer or section. Thus, a first element, component, region, layer or section discussed below could be termed a second element, component, region, layer or section without departing from the teachings of the present invention.

[0033] Embodiments of the invention are described herein with reference to cross-sectional and/or other illustrations that are schematic illustrations of idealized embodiments of the invention. As such, variations from the shapes of the illustrations as a result, for example, of manufacturing techniques and/or tolerances, are to be expected. Thus, embodiments of the invention should not be construed as limited to the particular shapes of regions illustrated herein but are to include deviations in shapes that result, for example, from manufacturing. For example, a region illustrated or described as a rectangle will, typically, have rounded or curved features due to normal manufacturing tolerances. Thus, the regions illustrated in the figures are schematic in nature and their shapes are not intended to illustrate the precise shape of a region of a device and are not intended to limit the scope of the invention, unless otherwise defined herein.

[0034] Unless otherwise defined herein, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this invention belongs. It will be further understood that terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the relevant art and this specification and will not be interpreted in an idealized or overly formal sense unless expressly so defined herein.

[0035] Some embodiments now will be described generally with reference to gallium nitride (GaN)-based light emitting diodes on silicon carbide (SiC)-based growth substrates for ease of understanding the description herein. However, it will be understood by those having skill in the art that other embodiments of the present invention may be based on a variety of different combinations of growth substrate and epitaxial layers. For example, combinations can include AlGaInP diodes on GaP growth substrates; InGaAs diodes on GaAs growth substrates; AlGaAs diodes on GaAs growth substrates; SiC diodes on SiC or sapphire (Al_2O_3) growth substrates and/or a Group III-nitride-based diode on gallium nitride, silicon carbide, aluminum nitride, sapphire, zinc oxide and/or other growth substrates. Moreover, in other embodiments, a growth substrate may not be present in the finished product. For example, the growth substrate may be removed after forming the light emitting diode, and/or a bonded substrate may be provided on the light emitting diode after removing the growth substrate. In some embodiments, the light emitting diodes may be gallium nitride-based LED devices manufactured and sold by Cree, Inc. of Durham, North Carolina.

[0036] Light Emitting Devices

[0037] Figures 1-2 provide detailed embodiments of representative light emitting devices that may be used with conformal gel layers according to various embodiments that will be described herein. However, many other embodiments of light emitting devices may be used with conformal gel layers, as will be described in detail below. Figures 1 and 2 correspond to Figures 1 and 2 of Application No. 13/112,502 to Emerson et al., entitled "*Gap Engineering for Flip-Chip Mounted Horizontal LEDs*", filed May 20, 2011, assigned to the assignee of the present application, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

[0038] Figure 1 is a cross-sectional view of a light emitting diode die and a packaged light emitting device. Referring to Figure 1, the light emitting diode die **100** includes a diode region **110** having first and second opposing faces **110a**, **110b**, respectively, and including therein an n-type layer **112** and a p-type layer **114**. Other layers or regions may be provided, which may include quantum wells, buffer layers, etc., that need not be described herein. An anode contact **160** ohmically contacts the p-type layer **114** and extends on a first face **110a**. The anode contact **160** may directly ohmically contact the p-type layer **114**, or may ohmically contact the p-type layer **114** by way of one or more conductive vias **162** and/or other intermediate layers. A cathode contact **170** ohmically contacts the n-type layer **112** and also extends on the first face **110a**. The cathode contact may directly ohmically contact the n-type layer **112**, or may ohmically contact the n-type layer **112** by way of one or more conductive vias **172** and/or other intermediate layers. As illustrated in Figure 1, the anode contact **160** and the cathode contact **170** that both extend on the first face **110a** are coplanar. The diode region **110** also may be referred to herein as an "LED epi region", because it is typically formed epitaxially on a substrate **120**. For example, a Group III-nitride based LED epi **110** may be formed on a silicon carbide growth substrate. In some embodiments, the growth substrate may be present in the finished product. In other embodiments, the growth substrate may be removed. In still other embodiments, another substrate may be provided that is different from the growth substrate, and the other substrate may be bonded to the LED after removing the growth substrate.

[0039] As also shown in Figure 1, a transparent substrate **120**, such as a transparent silicon carbide growth substrate or a transparent sapphire growth substrate, is included on the second face **110b** of the diode region **110**. The transparent substrate **120** includes a sidewall **120a** and may also include an inner face **120c** adjacent the second face **110b** of the diode region **110** and an outer face **120b**, remote from the inner face **120c**. The outer face **120b** is of smaller area than the inner face **120c**. In some embodiments, the

sidewall **120a** may be stepped, beveled and/or faceted, so as to provide the outer face **120b** that is of smaller area than the inner face **120c**. In other embodiments, as shown in Figure 1, the sidewall is an oblique sidewall **120a** that extends at an oblique angle θ , and in some embodiments at an obtuse angle, from the outer face **120b** towards the inner face **120c**. Non-oblique sidewalls and approximately equal faces **120b** and **120c** also may be provided.

[0040] Various embodiments of phosphor layers **140** and diode regions **110** may be provided. For example, in some embodiments, the diode region **110** is configured to emit blue light, for example light having a dominant wavelength of about 450-460nm, and the conformal layer comprises yellow phosphor, such as YAG:Ce phosphor having a peak wavelength of about 550nm. In other embodiments, the diode region **110** is configured to emit blue light upon energization thereof, as described above, and the conformal layer **140** may comprise a mixture of yellow phosphor and red phosphor, such as a CASN-based phosphor.

[0041] Continuing with the description of Figure 1, the LED die **100** may be combined with a mounting substrate, such as a submount **180**, and a lens **190** to provide a light emitting device **200**. The submount **180** may include a body **182** that may comprise aluminum nitride (AlN). In other embodiments, metal core substrates, printed circuit boards, lead frames and/or other conventional packaging substrates may be used to mount the LED die **100** in a flip-chip configuration. The submount **180** includes a submount face **182a**, and an anode pad **184** and a cathode pad **186** thereon. The anode and cathode pads may comprise silver-plated copper and/or other conductive materials. As illustrated in Figure 1, the LED die **100** is mounted on the submount **180**, such that the first face **110a** is adjacent the submount face **182a**, the outer face **110b** is remote from the submount **180**, the anode contact **184** is adjacent the anode pad **160**, and the cathode contact **186** is adjacent the cathode pad **170**. In some embodiments, a bonding layer, such as a eutectic gold/tin solder layer **188**, is used to electrically, thermally and mechanically connect the anode contact **160** to the anode pad **184**, and the cathode contact **170** to the cathode pad **186**. In other embodiments, direct attachment of the anode contact **160** to the anode pad **184**, and direct attachment of the cathode contact **170** to the cathode pad **186** may be provided, for example using thermocompression bonding and/or other techniques.

[0042] A packaged device anode **192** and a packaged device cathode **194** may be provided on a second face **182b** of the submount body **182**, and may be connected to the anode pad **184** and cathode pad **186**, respectively, using internal vias and/or conductive layers that extend on and/or around the submount body **182**.

[0043] Finally, the packaged light emitting device **200** may also include a lens **190** that extends from submount face **180a** to surround the LED die **100**. The lens **190** may be a molded plastic lens.

[0044] Figure 2 is a cross-sectional view of another LED die and packaged light emitting device. Compared to embodiments of Figure 1, the phosphor layer **140'** extends across the diode region **110** and/or on the first face **182** of the submount body **182**. Moreover, as shown in Figure 2, the submount **180** may include a layer **194** on the first face **182a** thereof. The layer **194** may be an extension of the anode pad **184** and the cathode pad **186** or may be distinct therefrom. In some embodiments, the layer **194** is a reflective layer that extends between the submount face **182a** and the conformal layer **140'** that includes phosphor that extends on the submount face **182a**. This reflective layer **194** can reflect light that passes through the phosphor layer that is on the submount face **182a** back toward the lens **190**, and can thereby increase efficiency of the LED.

[0045] Packaged light emitting devices as described above in connection with Figures 1 and 2 may be embodied as a Cree® XLamp® XP-E High-Efficiency White (HEW) LED, as described, for example, in the *Cree® XLamp® XP-E High-Efficiency White LEDs Data Sheet*, Publication No. CLD-DS34, Rev. 0, dated December 6, 2010, and available at cree.com/products/xlamp_xpe.asp, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

[0046] Figures 1-2 illustrate light emitting diode dies that are configured for flip-chip mounting on a mounting substrate. Various configurations of flip-chip mounted light emitting diode dies may be used in various embodiments described herein. Other light emitting devices according to various embodiments described herein may be configured for non-flip-chip mounting on a mounting substrate, as described and illustrated, for example, in U.S. Patent Application Publication 2011/0031502 to Bergmann et al. entitled "*Light Emitting Diodes Including Integrated Backside Reflector and Die Attach*", filed August 10, 2009, assigned to the assignee of the present application, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein. Moreover, other light emitting devices according to various embodiments described herein may be configured as vertical light emitting devices, as described and illustrated, for example, in U.S. Patent 6,791,119 to Slater, Jr et al., entitled "*Light Emitting Diodes Including Modifications for Light Extraction*", filed January 25, 2002, assigned to the assignee of the present application, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein.

[0047] Conformal Gel Layers for Light Emitting Diodes

[0048] Various embodiments of gel layers as described herein may be used with horizontal light emitting diode dies, in which both the anode and cathode contacts are on the same surface of the die, or vertical light emitting diode dies, in which the anode and cathode contacts are on opposite surfaces of the light emitting diode die. Moreover, gel layers according to various embodiments described herein may be used with horizontal LED dies that are mounted on a mounting substrate in a flip-chip (contacts adjacent the mounting substrate) or non-flip-chip (contacts remote from the mounting substrate) orientation. Similarly, for vertical devices, gel layers may be used for light emitting diode dies that are mounted on a mounting substrate with the anode contact adjacent the mounting substrate and the cathode contact remote from the mounting substrate, or with the cathode contact adjacent the mounting substrate and the anode contact remote from the mounting substrate. Yet other configurations of LED dies may be used.

[0049] Various embodiments described herein may arise from a recognition that a thin and/or conformal gel layer may be used to increase the reliability and/or provide other potential advantages when packaging light emitting diode dies on a mounting substrate. In some embodiments, the thin and/or conformal gel layer may be used to at least partially fill a gap between one or more bond regions that connects the light emitting diode die to the mounting substrate and the edge of the light emitting diode die, so as to prevent high modulus silicone that is used in the phosphor layer from entering into the gap under and around the perimeter of the light emitting diode die sufficiently to degrade the reliability of the bond between the light emitting diode die and the mounting substrate. Moreover, the low modulus thin and/or conformal gel layer may also be employed as a shock absorber or a buffer layer between the phosphor coating and/or lens and the LED die, to reduce stress on the die attach metal bonds during high temperature reflow and/or subsequent device operation. As used herein, "modulus" means an elastic modulus or a complex shear modulus, commonly referred to as G^* . The complex shear modulus includes more than one component, such as a storage modulus and a loss modulus. In the case of shear loading, it may also be referred to as a "dynamic modulus".

[0050] The gel layer according to various embodiments described herein may be contrasted with a glob of gel or other encapsulation material that may be applied to LEDs as described, for example, in U.S. Patent 6,590,235 to Carey et al., entitled *"High Stability Optical Encapsulation and Packaging for Light-Emitting Diodes in the Green, Blue, and Near UV Range"*. Specifically, a glob of gel that is applied to an LED is typically quite thick.

In contrast, a gel layer according to some embodiments described herein may be quite thin and may be less than about 20 μ m thick in some embodiments, less than about 10 μ m thick in other embodiments, and about 5 μ m or about 3 μ m thick in still other embodiments. The gel layer may also be a conformal gel layer in some embodiments. Moreover, a phosphor layer may be provided on the gel layer according to some embodiments described herein. In some embodiments, the gel layer and the phosphor layer both comprise silicone, but the phosphor layer is not a gel. In other embodiments, the gel layer is at least five times thinner than the phosphor layer. In still other embodiments, the gel layer has a modulus that is less than the phosphor layer and, in some embodiments, that is at least one, two or three orders of magnitude less than the phosphor layer.

[0051] It would also not be predictable to apply a conformal gel layer on the mounting substrate that extends at least partially into the gap, because the silicone-containing phosphor coating or silicone-containing molded lens that are typically used may already be regarded as providing stress relief. However, these silicone-containing coatings may have a relatively high modulus, and may degrade the package reliability during reflow or subsequent device operation, if they encroach into the gap. In contrast, by incorporating a conformal gel layer in the gap, the phosphor layer or molded lens may be prevented from encroaching into the gap. Moreover, the gel layer may exhibit sufficiently low modulus so as not to degrade reliability during reflow and/or subsequent device operation. In other embodiments, the conformal gel layer can be applied to light emitting diode dies in a cavity package and/or a planar package that uses a silicone dam to contain the phosphor layer, with the phosphor layer dispensed to fill the cavity around the gel-coated LED die. The low modulus of the gel layer can provide stress relief to the LED die, so as not to degrade reliability during reflow and/or subsequent device operation.

[0052] It would also not be predictable to use a conformal gel layer on an LED die between a phosphor layer and the LED die. Specifically, it is known that the LED die can provide heat sinking for the phosphor layer, and that it is desirable to anchor the phosphor layer to the LED die. Yet, an intermediate conformal gel layer between a conformal or non-conformal phosphor layer and the LED die can actually retain the heat sinking abilities of the LED die while enhancing the reliability of the device, by providing a buffer layer. Moreover, by being conformal to the LED die, anchoring of the phosphor layer and/or the lens may still take place.

[0053] Figure 3 is a cross-sectional view of a horizontal, flip-chip light emitting device, such as was illustrated in Figures 1 and 2, according to various embodiments

described herein. These light emitting devices **300** may include a mounting substrate **310** and a light emitting diode die **320** adjacent the mounting substrate, to define a gap **G** therebetween. The mounting substrate may correspond to the submount **180** and the light emitting die may correspond to the LED die **100** of Figures 1 and 2 in some embodiments. More specifically, a bond region **330** that may be formed by an anode and/or a cathode contact of the LED die **320** (for example, as shown by contacts **160** and/or **170** of Figures 1 and 2), an anode and/or a cathode pad of the mounting substrate **310** (for example, as shown by pads **184** and/or **186** of Figures 1 and 2), and/or a bond layer therebetween (for example, as shown by element **188** of Figures 1 and 2), is recessed from an edge of the LED die **320** to define the gap **G**. The bond region **330** may therefore provide mechanical connection and may also provide one or more electrical connections. A conformal gel layer **340** is provided on the mounting substrate **310** and includes opposing surfaces that both conform to a contour of the mounting substrate **310**. The conformal gel layer **340** extends at least partially into the gap **G**. In embodiments of Figure 3, the conformal gel layer **340** only partially fills the gap **G**. However, in other embodiments, the conformal gel layer **340** may entirely fill the gap **G** and, in still other embodiments, the conformal gel layer **340** may be thicker than the height of the gap **G**. In some embodiments, the conformal gel layer **340** is less than about 20 μ m thick. In other embodiments, it is less than about 10 μ m thick and, in still other embodiments, it is about 5 μ m or about 3 μ m thick. In other embodiments, the gel layer **340** need not be conformal when it is so thin.

[0054] As was described above, the conformal gel layer **340** includes opposing surfaces that both conform to a contour of the mounting substrate **310** and/or the LED die **320**. It will be understood that the conformal gel layer **340** need not conform to the contour of the mounting substrate and/or LED die on the entire surface thereof. For example, the conformal gel layer may be patterned so that it is not present on a portion of the mounting substrate/LED die or may be non-conformal on a portion of the mounting substrate/LED die. However, the conformal gel layer includes opposing surfaces that both conform to the contour of the mounting substrate/LED die over at least a portion thereof, for example adjacent the LED die in some embodiments, and in other embodiments surrounding the LED die.

[0055] Still referring to Figure 3, in some embodiments, one or more conformal phosphor layers **350** are provided on the conformal gel layer **340**, and a lens **360** may be provided or molded on the mounting substrate **310**. For example, the phosphor layer **350** may convert at least some blue light that is emitted from a blue LED **320** into yellow light

and/or red light, so as to provide the appearance of white light. In other embodiments, phosphor may be provided in the molded lens **360**, in an encapsulation material, as one or more conformal or non-conformal layers, or phosphor need not be provided at all. As was described above in connection with the conformal gel layer **340**, the conformal phosphor layer **350** need not be conformal over the entire contour of the mounting substrate or LED die.

[0056] The conformal gel layer **340** may provide a filler in the gap **G** that can prevent the phosphor layer **350** or the molded lens **360** from entering the gap **G** sufficiently to degrade operation of the light emitting device **300**.

[0057] In some embodiments, the conformal gel layer **340**, the phosphor layer **350** and the molded lens **360** may all comprise silicone. However, in some embodiments, the conformal phosphor layer **350** and molded lens **360** are not gels. For example, a Dow Corning Specification Sheet entitled "*Dow Corning LED SOLUTIONS Lighting the way to advanced materials and solutions*", Form No. 11-1679A-01, 2008, the disclosure of which is hereby incorporated herein by reference in its entirety as if set forth fully herein, describes various silicone-based gels, elastomers and resins that may be used for encapsulants, lens molding and overmolding. Normal refractive index and high refractive index materials may be provided. As shown, although various hardnesses may be attributed to the elastomers and resins, the gels have hardness that is so low as to be unmeasurable. In other embodiments, the gel may have a hardness of less than about 30 on the Shore A scale. The gel may also have an optical transmission of greater than about 95% and, in some embodiments, greater than about 98%, in the visible spectrum and a refractive index of greater than about 1.4 and, in some embodiments, greater than about 1.5.

[0058] As is well known to those having skill in the art, the hardness of plastics is commonly measured by a Shore[®] (Durometer) test or Rockwell hardness test. Both tests measure the resistance of plastics toward indentation and provide an empirical hardness value that may not necessarily correlate well to other properties or fundamental characteristics. Shore Hardness, using either the Shore A or Shore D scale, is generally used for rubbers/elastomers and is also commonly used for "softer" plastics, such as polyolefins, fluoropolymers and vinyls. The Shore A scale is generally used for "softer" rubbers, while the Shore D scale is generally used for "harder" ones. Many other Shore hardness scales, such as Shore O and Shore H hardness, exist but are less frequently used. As described in the above-cited Dow Corning Specification Sheet, the hardness of a gel is generally unmeasurable using any conventional test or scale.

[0059] In addition to having significantly lower hardness, a silicone-based gel may also have a significantly lower modulus compared to silicone-based elastomers and resins that were described above. The significantly lower modulus may be a primary factor in the ability of the gel to reduce or minimize stress on the light emitting diode die. For example, a Dow Corning silicone-based gel as described above may have a complex shear modulus (G^*) of about 0.009MPa at 25°C, while a comparable complex modulus for a silicone-based elastomer or resin may be about 12MPa at 25°C. Thus, a silicone-based gel may have a complex modulus that is lower than that of a silicone-based elastomer or resin, and in some embodiments at least about one, two or three orders of magnitude lower than that of a silicone-based elastomer or resin. While the preceding values were quoted at 25°C, the complex modulus behavior of the gel continues to be orders of magnitude lower than the elastomers or resins over wide temperature ranges. Accordingly, conformal gel layers as described herein may provide a low modulus layer that can provide both higher light output and better stress relief than elastomer-type or resin-type silicone formulations.

[0060] It will also be understood that the silicone-based gels described above are merely examples, and many other silicone or non-silicone-based gels may be used. In some embodiments of Figure 3, the conformal gel layer 350 may be selected from any of the gels, the phosphor layer may be selected from any of the elastomers, and the molded lens may be selected from any of the resins listed in the above-referenced Dow Corning Specification Sheet.

[0061] Figure 4 illustrates other embodiments of light emitting devices 400, wherein the conformal gel layer 340' also extends from the gap G onto the LED die 320 and, in some embodiments, covers the LED die 320. In embodiments of Figure 4, the phosphor layer 350' is a conformal phosphor layer. Accordingly, in embodiments of Figure 4, the conformal gel layer 340' fills the gap G and also provides a buffer layer between the conformal phosphor layer 350' and the LED die 320. In other embodiments, even if the gap G is not presented or is otherwise filled, the conformal gel layer 340' may form a buffer layer or shock absorber between the conformal phosphor layer 350' and the LED die 320. In other embodiments, phosphor may be provided in the molded lens 360, in an encapsulation material, as one or more conformal or non-conformal layers, or phosphor need not be provided at all.

[0062] In embodiments of Figure 4, the conformal gel layer 340' may be sufficiently thin so as to not adversely degrade performance of the light emitting device 400. More specifically, it is known that the LED die 320 can provide heat sinking to reduce

degradation of the phosphor in the phosphor layer **350'**. In some embodiments, the conformal gel layer **340'** may be sufficiently thermally conductive and sufficiently thin so as to allow effective heat sinking to take place. In some embodiments, the conformal phosphor layer **350'** may be between about 50 μ m and about 100 μ m thick and the conformal gel layer **340'** may be between about 3 μ m and about 10 μ m thick. In some embodiments, the gel layer is less than about 20 μ m thick. In other embodiments, the gel layer is less than about 10 μ m thick and, in still other embodiments, it is about 5 μ m or about 3 μ m thick. Accordingly, the conformal gel layer **340'** may be at least about five (5) times thinner than the conformal phosphor layer **350'** in some embodiments. In other embodiments, the gel layer **340** need not be conformal when it is so thin.

[0063] Figure 5 is a cross-sectional view of a light emitting device according to other embodiments described herein. As shown in Figure 5, these light emitting devices **500** include a horizontal LED die **320'** that is mounted in non-flip-chip configuration, as described, for example, in the above-cited U.S. Publication No. 2011/0031502, so that the anode and cathode contacts **332** and **334** are remote from the mounting substrate **310** and a bond region **330** that may not provide electrical contact is provided to mount the LED on the mounting substrate **310**. A conformal gel layer **340''** is provided that extends from the mounting substrate **310** onto the LED die **320'**.

[0064] In Figure 5, a gap **G** is not shown between the bond region **330** and the LED die **320**. Yet, the conformal gel layer **340''** can provide potential advantages nonetheless. In particular, a conformal or non-conformal phosphor layer (not shown in Figure 5) and/or the molded lens **360** may exert upward (separating) forces on the LED die **320'**, as shown by arrow **512**. This force may degrade the bond of the bond region **330** and may cause the LED die **320** to at least partially detach from the mounting substrate **310** during thermal cycling (reflow or subsequent operation) or may cause the bond to degrade even if it remains attached. This force may be caused by the Coefficient of Thermal Expansion (CTE) of the phosphor layer and/or molded lens. The conformal gel layer **340'** may provide a buffer layer against this degradation, due to its low hardness and low modulus. In other embodiments, phosphor may be provided in the molded lens **360**, in an encapsulation material, as one or more conformal or non-conformal layers, or phosphor need not be provided at all.

[0065] Figure 6 illustrates other embodiments of light emitting devices **600** wherein a vertical LED die **320''** includes one of the anode or cathode contact **610** adjacent the mounting substrate **310**, and the other of the anode or cathode contact **620** remote from

the mounting substrate **310**, as was illustrated, for example, in the above-cited U.S. Patent 6,791,119. A conformal gel layer **340'''** fills the gap **G** between the contact **610** and the edge of the LED die **320'**, and also provides a buffer layer for the phosphor layer **350'**. The phosphor layer **350'** may be conformal, semi-conformal (as illustrated) or non-conformal. In these embodiments, the conformal gel layer **340'''** can at least partially fill the gap **G**, if present, and can also reduce or prevent the LED die from lifting off due to forces generated by the thermal expansion of the phosphor layer **350'** or the dome **360**. In other embodiments of Figures 5 and 6, the sidewall walls of the LED die **320'/320''** may be orthogonal to the faces thereof or may form an obtuse angle with the mounting substrate **310**.

[0066] Figure 7 illustrates other embodiments of light emitting devices **700**. In these embodiments, a plurality of LED die **320'''** are mounted on a mounting substrate **310** using a bonding region **710** that may also provide one or more electrical contacts. Any of the embodiments of LED die that are described herein may be used. A conformal gel layer **340'''** is provided on the face of the mounting substrate **310** and on the LED dies **320'''**. A glob **350''** of phosphor is provided, as well as a molded lens **360**. Unexpectedly, in embodiments of Figure 7, it has been found that the conformal gel layer **340'''** can promote adhesion of the glob **350''** of phosphor and/or the lens **360** in the device **700**, by acting as a shock absorber against the effects of thermal expansion in the phosphor layer **350''** and/or the lens **360**. Also unexpectedly, the conformal gel layer **340'''** may be more effective than a non-conformal gel layer, such as may be provided by conventional encapsulant, by providing additional gripping surface to which the phosphor layer **350''** and/or lens **360** may adhere, and may also preserve the heat sinking abilities of the LED dies **320''**.

[0067] Various embodiments illustrated in Figures 3-7 and described herein can also provide a light emitting device that comprises a light emitting diode die and a gel layer that is less than about 20 μ m thick on the light emitting diode die. The gel layer may be a conformal layer including opposing surfaces that both conform to a contour of the light emitting diode die. In other embodiments, the gel layer is less than about 10 μ m thick and, in still other embodiments, the gel layer is about 3 μ m or about 5 μ m thick. A phosphor layer may be provided on the gel layer.

[0068] Yet other embodiments illustrated in Figures 3-7 and described herein can also provide a light emitting device that comprises a light emitting diode die, a gel layer on the light emitting diode die and a phosphor layer on the gel layer. The gel layer and the phosphor layer may both comprise silicone, but the phosphor layer is not a gel. Moreover, the gel layer may be at least five times thinner than the phosphor layer. Furthermore, the gel

layer may have a modulus that is less than the phosphor layer and, in some embodiments, the gel layer has a modulus that is at least one, two or three orders of magnitude less than the phosphor layer.

[0069] Fabrication

[0070] Methods of fabricating light emitting devices according to various embodiments described herein will now be described. In particular, referring to Figure 8 at Block **810**, a mounting substrate having a light emitting diode die mounted thereon is conformally gel coated using, for example, various processes that will be described below. Then, referring to Block **820**, if a conformal phosphor coating is to be provided, phosphor is conformally coated on the mounting substrate having a light emitting diode die mounted thereon that was conformally gel coated in Block **810**. In other embodiments, a non-conformal phosphor coating may be applied or no phosphor coating may be applied. Further processing is then performed at Block **830**, for example to mold a lens, etc. It will be understood that the operations of Blocks **820** and **830** may be performed out of order from that shown in Figure 8, and one of these blocks may also be omitted. Accordingly, Figure 8 illustrates methods of fabricating a light emitting device wherein a mounting substrate having a light emitting diode die mounted thereon is conformally gel coated and then the gel-coated mounting substrate is phosphor-coated and/or a lens is molded thereon.

[0071] Various techniques may be used to conformally gel coat the mounting substrate having a light emitting die mounted thereon (Block **810**). Specifically, in some embodiments, a thin conformal gel coat may be applied by diluting a gel with a solvent, such as xylene, which can then evaporate off, leaving a thin conformal gel coating layer. A spray process, a drop dispense and/or other process may be used. In a spray process, the gel that is diluted in the solvent is sprayed onto the mounting substrate having the light emitting diode die mounted thereon, such that at least some of the solvent evaporates. Multiple spray passes may be used. In a dispensing process, the gel that is diluted in the solvent may be dispensed onto the mounting substrate having the light emitting diode die mounted thereon, and then at least some of the solvent may be evaporated, for example by heating. Multiple dispenses may be used. Other techniques of forming a conformal gel coating may be used.

[0072] Experimental Results

[0073] The following examples shall be regarded as merely illustrative and shall not be construed as limiting the invention.

[0074] Figure 9A is a photograph of an array of 16 LED die on a mounting substrate. A lens was then molded on the mounting substrate of Figure 9A, and the device

was subject to a reflow in a standard reflow oven using a typical reflow profile with a 260°C peak for lead-free solder attach. The lens was then removed. Figure 9B illustrates the result after lens removal. As shown, only five of the LED die remain attached to the substrate, so that eleven of the die came off upon removal of the lens, indicating severe degradation of the die attach.

[0075] Figure 9C illustrates an identical device as Figure 9A, except that a conformal gel layer of Dow OE-6450 gel, about 7µm thick, was applied before molding the lens. The device was then subject to fifteen (15) reflows in the standard reflow oven using the typical reflow profile with a 260° peak for lead-free solder attach, and the lens was then removed. No die attach failures were found, as illustrated in Figure 9C. Figure 9D illustrates an identical device as Figure 9A, except the conformal gel layer of Figure 9C was coated with a conformal phosphor layer, about 50µm thick, prior to molding the lens. Again, fifteen (15) reflows in the standard reflow oven using the typical reflow profile with a 260°C peak for lead-free solder attach were performed prior to removing the lens. Again, no die attach failures were found. Accordingly, a conformal gel layer according to various embodiments described herein can improve the reliability of a light emitting device and reduce or prevent die attached degradation due to subsequent processing and/or device operation.

[0076] Additional Discussion

[0077] Additional discussion of various embodiments described herein will now be provided. Various embodiments described herein can provide a thermally robust LED package that may, in some embodiments, use horizontal LED dies that are mounted on mounting substrates, such that the anode and cathode contacts are adjacent the mounting substrate. A thin conformal gel coat is applied to the die or die arrays by, for example, diluting the gel with xylene, which evaporates off, leaving a very thin layer. The gel coat may be applied with a heated spray process or a drop dispense of highly diluted silicone (for example, five parts xylene by volume to one part silicone) followed by heating. Coating can be performed, for example, prior to phosphor deposition for white light emitting devices or just prior to lens molding for blue light emitting devices. The gel can provide a buffer to the harder silicones used for the phosphor coating or lens molding, to reduce or minimize stress on the die attach metal bonds during temperature reflow and/or package operation.

[0078] For applications where the thin, conformal gel coating is applied under the conformal phosphor layer, the thin conforming gel coating may maintain the conformal phosphor layer very close to the LED die surface, to thereby provide similar heat sinking as that of a part without the gel.

[0079] Conventionally, a glob or fill approach has been used to cover the LED die with a gel-like material under a harder lens material. Some embodiments described herein can provide similar benefits as conventional glob or fill gel, while allowing improved lens adhesion, particularly for small die arrays. In such small die arrays, the topography may be maintained to provide better mechanical attachment of the phosphor layers and/or lens. It may also maintain the necessary heat sinking of the phosphor layer to reduce or prevent heating and charring.

[0080] Moreover, a gel layer according to various embodiments described herein may provide unexpected advantages for small LED dies. In particular, as the die size is reduced from about 1mm^2 , the potential for negative impact on the die attach due to the silicone resin or elastomer properties is increased, since the die attach area becomes increasingly smaller. In addition to a reduction in the absolute die attach area, the relative die attach area as a percentage of total die area is also generally reduced, as the electrode spacing, electrode setbacks from the device edges and/or street widths may follow the same design rules as the larger dies. Accordingly, the ratios of the perimeter gap area and electrode gap area under the die relative to the die attach area generally increase as the die is made smaller, exacerbating the impact of silicone resin or elastomer penetration in these areas given the reduction in absolute die attach area. Die sizes below about 0.25mm^2 may be particularly sensitive. For example, on a $350 \times 470\text{mm}$ direct attach die, the die attach pads represent about 58% of the total die area. However, on the $240 \times 320\text{mm}$ direct attach die shown in Figures 9A-9D, the die attach area is reduced to about 48% of the total die area. For reference, on a 1mm^2 die, the die attach area is greater than about 80% of the die area. Accordingly, a gel layer according to various embodiments described herein may be particularly useful as LED die size decreases.

[0081] Gel Underfill Layers

[0082] Various embodiments described above can provide conformal and/or thin gel layers for light emitting devices. However, there may be other applications where it is desirable to restrict the gel to an underfill layer in the gap(s) between the light emitting diode die(s) and the mounting substrate that is adjacent thereto, without completely covering the LED die(s), e.g., without providing substantial amounts of gel on the outer face of the LED die(s) and without providing substantial amounts of gel on the substrate substantially beyond the array of LED die(s). Thus, it may be desirable to provide a gel underfill at the base of the LED die(s) that may extend at least partially onto the sidewalls of the LED die(s), but that does not extend on the substrate substantially beyond the LED die(s) and also does not extend

substantially on an outer face of the LED die(s). Leaving most of the outer surface of the LED die(s) substantially bare and leaving the substrate beyond the LED die(s) substantially bare can improve or maximize thermal heat sinking and adhesion of a phosphor layer and/or an overmolded lens to the light emitting device.

[0083] Figure 10 is a flowchart of fabricating a light emitting device according to various embodiments provided herein. A mounting substrate and one or more LED die(s) adjacent the mounting substrate are provided, to define a gap between a respective LED die(s) and the mounting substrate that is adjacent thereto. As used herein, more than one LED die that is provided adjacent the mounting substrate is also referred to as an "array" of LED dies.

[0084] Referring to Block **1010**, a gel that is diluted in a solvent is applied on the substrate and on the LED die(s). The gel may be applied by dispensing at least one drop of gel that is diluted in the solvent, by spraying the gel that is diluted in the solvent and/or by other application techniques. In some embodiments, the gel may be diluted in the solvent at a ratio of about 1:4-5 by volume.

[0085] Then, at Block **1020**, at least some of the solvent is evaporated so that the gel remains in the gaps, but does not completely cover the LED die(s). In some embodiments, the gel substantially recedes from the substrate beyond the array of LED die(s), and also substantially recedes from an outer face of the LED die(s). A conformal or nonconformal layer of phosphor and/or a lens may then be applied and/or attached at Block **1030**, according to any of the techniques described above and/or using other techniques.

[0086] Various embodiments described herein can provide a thermally robust light emitting device. A gel underfill is formed at the base of the LED die(s) by applying a solution of highly diluted gel to the LED die(s). As the solvent is driven off by evaporation, surface tension and/or other forces pulls the gel substantially off the outer die face(s) and off the mounting substrate substantially beyond the LED die(s), forming a gel underfill layer around the base of the LED die(s). The level of filling around and between the LED dies can be varied based on, for example, the initial dispense volume and/or the ratio of solvent to gel. Thus, the gel does not completely cover the LED die(s).

[0087] By leaving the outer face(s) of the LED die(s) substantially bare and by leaving the substrate beyond the LED die(s) substantially bare, according to some embodiments described herein, improved or maximized thermal heat sinking and adhesion of a phosphor layer and/or overmolded lens may be provided. At the same time, the gel underfill layer can reduce or prevent the harder encapsulants typically used in the phosphor

layer and/or lens molding from penetrating in the gap under the LED die(s), to thereby reduce or minimize stress on the die attach metal bonds during high temperature reflow and/or device operation.

[0088] Accordingly, the underfill may be restricted to the base of die(s) and the die face(s), and the substrate beyond the die(s) may be left substantially bare, even though the gel solution is applied all over the substrate and the outer face(s) of the die(s). Given the LED die size, geometry and packing density, it may be very difficult to provide conventional underfill dispense around the perimeter of the LED die(s). However, with the outer face(s) substantially bare according to various embodiments described herein, the phosphor and/or lens can be in intimate contact with the die(s) to increase or maximize thermal heat sinking and adhesion. The surface tension also can restrict the coating area to the die(s), leaving substantially no or minimal gel on the substrate face outside the die(s). This allows the phosphor layer or lens to attach to the substrate and outer die face(s), which can provide similar lens attachment strength as a package with no gel underfill.

[0089] Figure 11 is a cross-sectional view of a light emitting device according to various embodiments described herein, and may correspond to a light emitting device after a gel is applied at Block 1010 of Figure 10, but before evaporation at Block 1020 of Figure 10.

[0090] Specifically, referring to Figure 11, an array of LED dies 320''' is provided adjacent a mounting substrate 310 to define a gap G between a respective LED die 320''' and the mounting substrate 310 that is adjacent thereto. The gap G may be established by a bonding region 710, as was described above. As shown in Figure 11, one or more LEDs 320''' may be provided. The LEDs 320''' may be identical or different therebetween. For example, as shown in Figure 11, the LED sidewalls may be vertical (orthogonal), oblique (obtuse or acute) or beveled. A gel that is diluted in a solvent 1110 is provided on the substrate 310 and on the LED die(s) 320'''. The gel that is diluted in a solvent may be applied using a heated or unheated spray process or a heated or unheated drop dispense of highly diluted silicone in a solvent. For example, about four to five parts xylene by volume to about one part silicone gel may be used. Figure 11 illustrates a drop profile of the gel layer that is diluted in solvent that may be obtained, for example, using drop dispensing. When spraying is used, a conformal, semiconformal or nonconformal gel layer that is diluted in a solvent may be produced.

[0091] Figures 12-15 are cross-sectional views of light emitting devices according to various embodiments described herein, and may correspond to light emitting devices after evaporating at least some of the solvent at Block 1020 of Figure 10. In all of the

embodiments of Figures 12-15, at least some of the solvent **1110** is evaporated so that the gel remains in the gap(s) **G**, but does not completely cover the LED die(s) **320'''**.

[0092] Referring now to Figure 12, at least some of the solvent **1110** is evaporated, for example at room temperature or above, so that the gel **1110a** remains in the gap(s) **G**, but substantially recedes from the substrate **310** beyond the LED die(s) **320'''** and also substantially recedes from an outer face of the LED die(s) **320'''**. As also shown in Figure 12, the gel may also fill the gap(s) **G**. Moreover, as also shown, the gel may also extend on the substrate **310** between adjacent LED dies **320'''** in the array and may also extend fully onto sidewalls of the LED die(s) **320'''**.

[0093] In Figure 12, the gel layer **1110a** extends along the entire sidewalls of the LED die(s) **320'''**. In contrast, in Figure 13, the gel layer **1110b** extends only partially onto the sidewalls of the LED die(s) **320'''**. Moreover, in Figure 14, the gel layer **1110c** does not extend onto the LED die sidewalls at all. Finally, in Figure 15, the gel layer **1110d** does not extend fully onto the substrate between adjacent LED dies **320'''**.

[0094] Thus, during evaporation, the gel remains in the gap(s) **G**, but substantially recedes from the substrate **310** beyond the light emitting diode die(s) and also substantially recedes from outer face(s) of the LED die(s) (Figures 12-15). The gel may also remain between adjacent LED die(s) (Figures 12-14) or may at least partially recede from between the adjacent LED die(s) (Figure 14). The LED gel may also remain fully (Figure 12) or partially (Figure 13) on the sidewalls of the LED die(s) or may substantially recede from the sidewalls of the LED die(s) (Figures 14-15).

[0095] The amount by which the gel recedes may be governed by many factors, including, but not limited to, the geometry and material compositions of the substrate, the LEDs and the bond regions; the composition, volume and wettability of the gel relative to these regions; the composition and volume of the solvent; the relative volumes of gel and solvent; and/or the evaporation conditions, such as time and temperature. For example, the gel may substantially recede from a reflective surface of the substrate, that comprise, for example, silver, aluminum and/or reflective ceramics such as Al_2O_3 .

[0096] Figures 12-16 also illustrate light emitting devices according to various embodiments described herein that include a mounting substrate **310** and one or more (an array) of LED dies **320'''** adjacent the mounting substrate **310**, to define a gap **G** between a respective LED die **320'''** and the mounting substrate **310** that is adjacent thereto, wherein the gap **G** may be defined by one or more bond regions **710**. A gel layer **1110a**, **1110b**, **1110c** and/or **1110d** is provided on the mounting substrate **310** that extends at least partially in the

gaps **G** between the LED die(s) **320'''** and the substrate **310** adjacent thereto, but does not completely cover the LED die(s) **320'''**. In some embodiments, the gel layer does not extend on the substrate **310** substantially beyond the LED die(s) **320'''** and also does not extend substantially on an outer face of the LED die(s) **320'''**. The gel layer may fill the gaps, as shown in Figures 12-15; may extend between adjacent LED dies in the array, as shown in Figures 12-14; may extend fully on sidewalls of the LED die(s), as shown in Figure 12; may extend partially on the sidewalls, as shown in Figure 13; or may not extend substantially on the sidewalls, as shown in Figure 15.

[0097] Figures 16-19 are cross-sectional views of LED devices according to various other embodiments described herein, after application of phosphor and/or a lens at Block **1030** of Figure 10. These figures are based on the structure of Figure 14. However, phosphor and/or a lens may be applied to the structures of Figures 12-13 and/or 15 in other embodiments.

[0098] Referring to Figure 16, a conformal or semiconformal phosphor layer **350** is applied, for example using techniques described above, that extends directly on the substrate **310** substantially beyond the LED die(s) and directly on the outer face(s) of the LED die(s). In Figure 17, a nonconformal phosphor layer **350''** is applied, for example using techniques described above, that extends directly on the substrate **310** substantially beyond the LED die(s) and directly on the outer face(s) of the LED die(s). Alternatively, in Figure 18, a conformal or semiconformal phosphor layer **350** may be applied that is directly on the substrate substantially beyond the array of LED die(s) and directly on the outer face(s) of the LED die(s) **320'''**, and a lens **360** may be applied, for example by molding, on the phosphor layer **350**. Finally, in Figure 19, a lens **360** is applied or molded on the substrate **310** substantially beyond the LED die(s) **320'''** and directly on the outer face(s) of the LED die(s) **320'''**. Phosphor may be included in and/or on the lens **360**.

[0099] Figures 20-22 are optical microscope images of light emitting devices according to various embodiments described herein. Figure 20 corresponds to Block **1010** of Figure 10, wherein a wet, highly diluted 4:1 solution of xylene:silicone gel is dispensed on top of a direct attach LED die array. Surface tension keeps the fluid held tight to the array.

[00100] Figures 21 and 22 illustrate light emitting devices after evaporating pursuant to Block **1020** of Figure 10. Heat was applied, for example, at about 150°C for about 1-2 hours to drive off the solvent and cure the gel. In some embodiments, an initial one-hour cure may be provided at about 150°C, followed by an additional one-hour cure at about 150°C after phosphor and/or lens application. The solvent evaporation and receding of

the gel may take place in the first few minutes of the initial cure. As shown in Figure 21, the gel has substantially receded from the substrate beyond the array of LED die(s) (a discoloration is shown where the gel/solvent originally was present), and also substantially recedes from the outer faces (tops) of the LED dies. The gel remains in the gaps and also remains on the substrate between adjacent LED dies.

[00101] Figure 22 is a more magnified optical microscope image showing the formation of the gel coating **1110c** around the bases of the LED dies and between the LED dies. As shown, the outer (top) surfaces of the LED dies and the remote (upper) surfaces of the sidewalls are substantially bare.

[00102] Figures 23-25 illustrate Scanning Electron Microscope (SEM) images of light emitting devices according to various embodiments described herein. Specifically, Figure 23 is a tilted SEM image showing the gel formation around the bases of the dies, extending to the substrate and extending between the dies, with minimal amounts of gel seen on the remote (upper) surfaces of the sidewalls and on the outer faces (tops) of the dies. Figure 24 is an analogous plan view of the SEM image showing the gel between the dies with minimal amounts of gel on the upper surfaces of the sidewalls and on the tops of the LED dies. Figure 25 is an analogous SEM image at a lower magnification, again showing the gel between the dies with minimal amounts of gel on the upper surfaces of the sidewalls and on the tops of the dies.

[00103] Figures 26-27 are Electron Diffraction Spectroscopy (EDS) spectra of light emitting devices according to various embodiments described herein. Specifically, Figure 26 is an EDS taken on the top (outer) face of the LED die. Figure 26 illustrates a silicon carbide composition of the LED die, with a low carbon (C) peak that confirms minimal gel presence on the outer face. Note that the platinum (Pt) peak is from a thin conductive coating that is applied for SEM purposes. In contrast, Figure 27 is an EDS spectrum taken between the dies, to show an increased carbon peak from the presence of the silicone gel between the dies.

[00104] Without wishing to be bound by any theory of operation, surface tension and/or other forces in a gel diluted in a solvent may be used to cause selective receding of the gel during evaporation of the solvent, so that the gel does not completely cover the LED dies and in some embodiments substantially recedes from the substrate beyond the array of LED dies, and also substantially recedes from outer faces of the LED dies, but remains in the gaps at the bases of the LED dies, and may also remain on the substrate between adjacent LED dies and/or at least partially on the LED die sidewalls. The gel may thereby be blanket-applied by drop dispensing, spray coating and/or other blanket techniques, yet the final

product may only have gel where it is desired and may have substantially no gel in areas where it is not desired for thermal and/or structural purposes.

[00105] Many different embodiments have been disclosed herein, in connection with the above description and the drawings. It will be understood that it would be unduly repetitious and obfuscating to literally describe and illustrate every combination and subcombination of these embodiments. Accordingly, the present specification, including the drawings, shall be construed to constitute a complete written description of all combinations and subcombinations of the embodiments described herein, and of the manner and process of making and using them, and shall support claims to any such combination or subcombination.

[00106] In the drawings and specification, there have been disclosed embodiments of the invention and, although specific terms are employed, they are used in a generic and descriptive sense only and not for purposes of limitation, the scope of the invention being set forth in the following claims.

WHAT IS CLAIMED IS:

1. A light emitting device comprising:
a mounting substrate;
a light emitting diode die adjacent the mounting substrate to define a gap
therebetween; and
a conformal gel layer on the mounting substrate that extends at least partially into the gap, the conformal gel layer including opposing surfaces that both conform to a contour of the mounting substrate.
2. A light emitting device according to Claim 1 wherein the conformal gel layer also extends from the gap onto the light emitting diode die.
3. A light emitting device according to Claim 2 wherein the opposing surfaces of the conformal gel layer also both conform to a contour of the light emitting diode die.
4. A light emitting device according to Claim 1 further comprising a bond region that connects the light emitting diode die to the mounting substrate and that is recessed from an edge of the light emitting diode die to define the gap, the conformal gel layer filling the gap.
5. A light emitting device according to Claim 3 further comprising a conformal phosphor layer on the conformal gel layer that extends onto the light emitting diode die, the conformal phosphor layer including opposing surfaces that both conform to the contour of the light emitting diode die.
6. A light emitting device according to Claim 5 further comprising a lens on the conformal phosphor layer.
7. A light emitting device according to Claim 3 further comprising a lens on the conformal gel layer.
8. A light emitting device according to Claim 5 wherein the conformal gel layer and the conformal phosphor layer both comprise silicone, but the conformal phosphor layer is not a gel.

9. A light emitting device according to Claim 8 wherein the conformal gel layer is at least five times thinner than the conformal phosphor layer.

10. A light emitting device comprising:
a mounting substrate;
a light emitting diode die adjacent the mounting substrate;
a bond region that connects the light emitting diode die to the mounting substrate and that is recessed from an edge of the light emitting diode die to define a gap;
a phosphor layer that extends from the mounting substrate, across the gap and onto the light emitting diode die; and
a filler in the gap that is configured to prevent the phosphor layer from entering the gap sufficiently to degrade operation of the light emitting device.

11. A light emitting device according to Claim 10 wherein the filler also extends from the gap between the phosphor layer and the mounting substrate.

12. A light emitting device according to Claim 11 wherein the filler also extends from the gap between the phosphor layer and the light emitting diode die.

13. A light emitting device comprising:
a mounting substrate;
a light emitting diode die on the mounting substrate; and
a conformal gel layer on the mounting substrate that extends at least partially onto the light emitting diode die, the conformal gel layer including opposing surfaces that both conform to a contour of the mounting substrate and the light emitting diode die.

14. A light emitting device according to Claim 13 further comprising a conformal phosphor layer on the conformal gel layer, the conformal phosphor layer including opposing surfaces that both conform to a contour of the mounting substrate and the light emitting diode die.

15. A light emitting device according to Claim 13 further comprising a lens on the conformal gel layer.

16. A light emitting device according to Claim 14 further comprising a lens on the conformal phosphor layer.

17. A light emitting device according to Claim 14 wherein the conformal gel layer and the conformal phosphor layer both comprise silicone, but the conformal phosphor layer is not a gel.

18. A light emitting device according to Claim 17 wherein the conformal gel layer is at least five times thinner than the conformal phosphor layer.

19. A light emitting device according to Claim 13 further comprising a phosphor layer on the conformal gel layer.

20. A light emitting device comprising:
a light emitting diode die; and
a gel layer that is less than about 20 μ m thick on the light emitting diode die.

21. A light emitting device according to Claim 20 wherein the gel layer is a conformal gel layer including opposing surfaces that both conform to a contour of the light emitting diode die.

22. A light emitting device according to Claim 20 wherein the gel layer is less than about 10 μ m thick.

23. A light emitting device according to Claim 20 wherein the gel layer is about 5 μ m thick.

24. A light emitting device according to Claim 20 further comprising a phosphor layer on the gel layer.

25. A light emitting device comprising:
a light emitting diode die;
a gel layer on the light emitting diode die; and

a phosphor layer on the gel layer.

26. A light emitting device according to Claim 25 wherein the gel layer and the phosphor layer both comprise silicone, but the phosphor layer is not a gel.

27. A light emitting device according to Claim 26 wherein the gel layer is at least five times thinner than the phosphor layer.

28. A light emitting device according to Claim 26 wherein the gel layer has a modulus that is less than the phosphor layer.

29. A light emitting device according to Claim 26 wherein the gel layer has a modulus that is at least an order of magnitude less than the phosphor layer.

30. A method of fabricating a light emitting device comprising:
conformally gel coating a mounting substrate having a light emitting diode die mounted thereon; and then
phosphor coating the mounting substrate and/or placing a lens on the mounting substrate having the light emitting diode die mounted thereon that was conformally gel coated.

31. A method according to Claim 30 wherein conformally gel coating comprises:
applying gel that is diluted in a solvent to the mounting substrate having the light emitting diode die mounted thereon.

32. A method according to Claim 31 wherein the applying gel comprises spraying the gel that is diluted in a solvent onto the mounting substrate having the light emitting diode die mounted thereon, such that at least some of the solvent evaporates.

33. A method according to Claim 31 wherein the applying gel comprises dispensing the gel that is diluted in a solvent onto the mounting substrate having the light emitting diode die mounted thereon and then evaporating at least some of the solvent.

34. A method according to Claim 30 wherein the gel coating, the phosphor coating and the lens all comprise silicone, but the phosphor coating and the lens are not gels.

35. A light emitting device comprising:
a mounting substrate;
an array of light emitting diode dies adjacent the mounting substrate to define a gap between a respective light emitting diode die and the mounting substrate that is adjacent thereto; and
a gel layer on the mounting substrate that extends at least partially in the gaps between the light emitting diode dies and the substrate adjacent thereto but does not completely cover the light emitting diode dies.

36. A light emitting device according to Claim 35 wherein the gel layer does not extend on the substrate substantially beyond the array of light emitting diode dies and also does not extend substantially on an outer face of the light emitting diode dies.

37. A light emitting device according to Claim 35 further comprising an array of bond regions, a respective one of which connects a respective light emitting diode die to the mounting substrate, a respective bond region being recessed from an edge of a respective light emitting diode die to define a respective gap.

38. A light emitting device according to Claim 37 wherein the gel layer fills the gaps.

39. A light emitting device according to Claim 38 wherein the gel layer also extends between adjacent light emitting diode dies in the array.

40. A light emitting device according to Claim 35 wherein the gel layer also extends between adjacent light emitting diode dies in the array.

41. A light emitting device according to Claim 36 wherein the gel layer also extends at least partially on sidewalls of the light emitting diode dies.

42. A light emitting device according to Claim 35 further comprising a phosphor layer directly on the substrate that extends beyond the array of light emitting diode dies and that also extends directly on the outer faces of the light emitting diode dies.

43. A light emitting device according to Claim 35 further comprising a lens that spans the array of light emitting diode dies and that extends directly on the substrate beyond the array of light emitting diode dies and directly on the outer faces of the light emitting diode dies.

44. A light emitting device according to Claim 36 wherein the gel does not extend on reflective areas of the substrate substantially beyond the array of light emitting diode dies.

45. A light emitting device comprising:
a mounting substrate;
a light emitting diode die adjacent the mounting substrate to define a gap between the light emitting diode die and the mounting substrate that is adjacent thereto; and
a gel layer on the mounting substrate that extends at least partially in the gap between the light emitting diode die and the substrate adjacent thereto but does not completely cover the light emitting diode die.

46. A light emitting device according to Claim 45 wherein the gel layer does not extend on the substrate substantially beyond the light emitting diode die and also does not extend substantially on an outer face of the light emitting diode die.

47. A light emitting device according to Claim 45 wherein the gel layer fills the gap.

48. A light emitting device according to Claim 46 wherein the gel layer also extends at least partially on sidewalls of the light emitting diode die.

49. A light emitting device according to Claim 45 further comprising a phosphor layer directly on the substrate beyond the light emitting diode die and directly on the outer face of the light emitting diode die.

50. A light emitting device according to Claim 45 further comprising a lens that spans the light emitting diode die and that extends directly on the substrate beyond the light emitting diode die and directly on the outer face of the light emitting diode die.

51. A light emitting device according to Claim 46 wherein the gel does not extend on reflective areas of the substrate substantially beyond the light emitting diode die.

52. A method of fabricating a light emitting device comprising:
providing a mounting substrate and an array of light emitting diode dies adjacent the mounting substrate to define a gap between a respective light emitting diode die and the mounting substrate that is adjacent thereto;

applying a gel that is diluted in a solvent on the substrate and on the array of light emitting diode dies; and

evaporating at least some of the solvent so that the gel remains in the gaps but does not completely cover the light emitting diode dies.

53. A method according to Claim 52 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gaps but substantially recedes from the substrate beyond the array of light emitting diode dies and also substantially recedes from on an outer face of the light emitting diode dies.

54. A method according to Claim 52 wherein the applying comprises dispensing at least one drop of gel that is diluted in the solvent on the substrate and on the array of light emitting diode dies.

55. A method according to Claim 52 wherein the applying comprises spraying the gel that is diluted in the solvent on the substrate and on the array of light emitting diode dies.

56. A method according to Claim 52 wherein the gel is diluted in the solvent at a ratio of about 1:4-5 by volume.

57. A method according to Claim 52 wherein the providing comprises providing a mounting substrate, an array of light emitting diode dies adjacent the mounting substrate and an array of bond regions, a respective one of which connects a respective light emitting diode

die to the mounting substrate, a respective bond region being recessed from an edge of a respective light emitting diode die to define a respective gap.

58. A method according to Claim 53 wherein the evaporating comprises evaporating at least some of the solvent so that the gel fills the gaps but substantially recedes from the substrate beyond the array of light emitting diode dies and also substantially recedes from on an outer face of the light emitting diode dies.

59. A method according to Claim 53 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gaps and on the substrate between adjacent light emitting diode dies but substantially recedes from the substrate beyond the array of light emitting diode dies and also substantially recedes from on an outer face of the light emitting diode dies.

60. A method according to Claim 53 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gaps and at least partially on sidewalls of the light emitting diode dies but substantially recedes from the substrate beyond the array of light emitting diode dies and also substantially recedes from on an outer face of the light emitting diode dies.

61. A method according to Claim 53 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gaps but substantially recedes from reflective areas of the substrate beyond the array of light emitting diode dies and also substantially recedes from on an outer face of the light emitting diode dies.

62. A method according to Claim 52 wherein the evaporating is followed by applying phosphor directly on the substrate beyond the array of light emitting diode die and directly on the outer faces of the light emitting diode dies.

63. A method according to Claim 52 wherein the evaporating is followed by attaching a lens that spans the array of light emitting diode dies and that extends directly on the substrate beyond the array of light emitting diode dies and directly on the outer faces of the light emitting diode dies.

64. A method of fabricating a light emitting device comprising:
providing a mounting substrate and a light emitting diode die adjacent the mounting substrate to define a gap between the light emitting diode die and the mounting substrate that is adjacent thereto;
applying a gel that is diluted in a solvent on the substrate and on the light emitting diode die; and
evaporating at least some of the solvent so that the gel remains in the gap but does not completely cover the light emitting diode die.

65. A method according to Claim 64 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gap but substantially recedes from the substrate beyond the light emitting diode die and also substantially recedes from an outer face of the light emitting diode die.

66. A method according to Claim 64 wherein the applying comprises dispensing at least one drop of gel that is diluted in the solvent on the substrate and on the light emitting diode die.

67. A method according to Claim 64 wherein the applying comprises spraying the gel that is diluted in the solvent on the substrate and on the light emitting diode die.

68. A method according to Claim 65 wherein the evaporating comprises evaporating at least some of the solvent so that the gel fills the gap but substantially recedes from the substrate beyond the light emitting diode die and also substantially recedes from on an outer face of the light emitting diode die.

69. A method according to Claim 65 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gap and at least partially on sidewalls of the light emitting diode die but substantially recedes from the substrate beyond the array of light emitting diode die and also substantially recedes from on an outer face of the light emitting diode die.

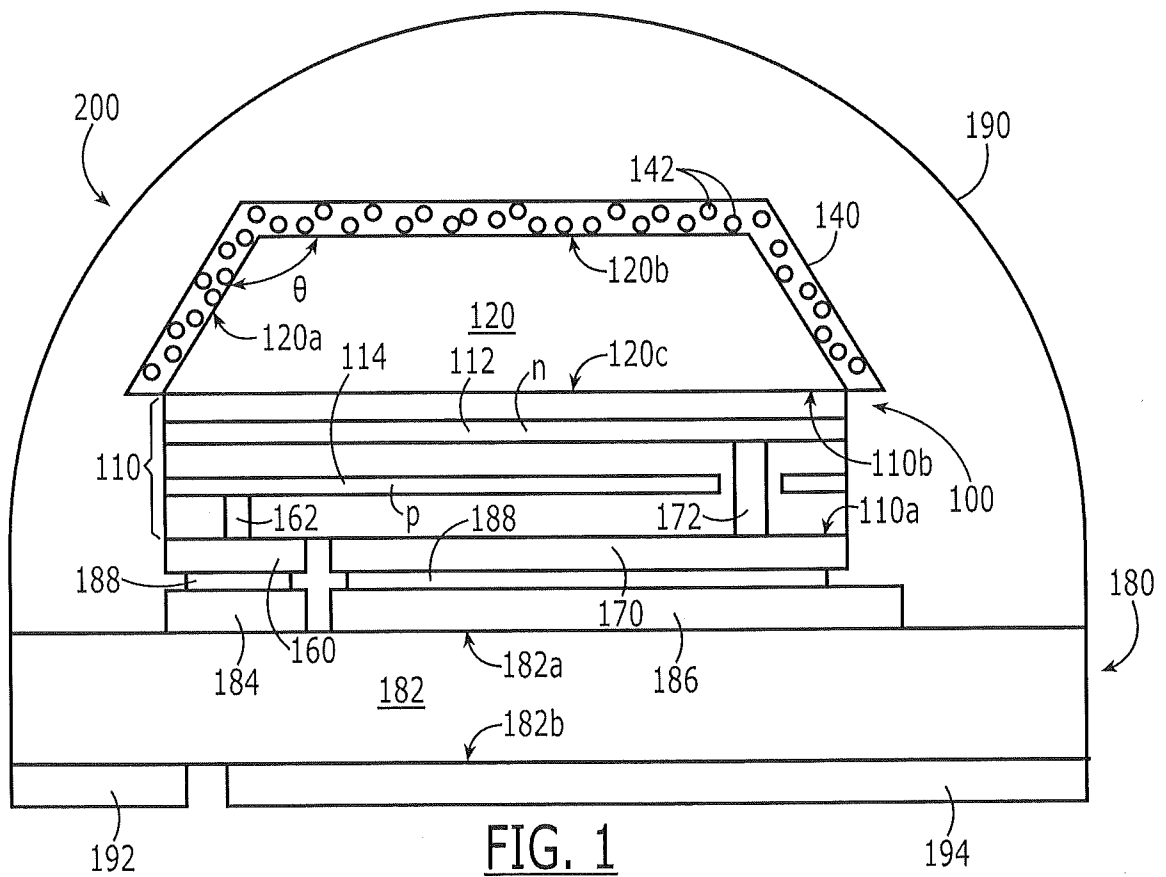
70. A method according to Claim 65 wherein the evaporating comprises evaporating at least some of the solvent so that the gel remains in the gap but substantially

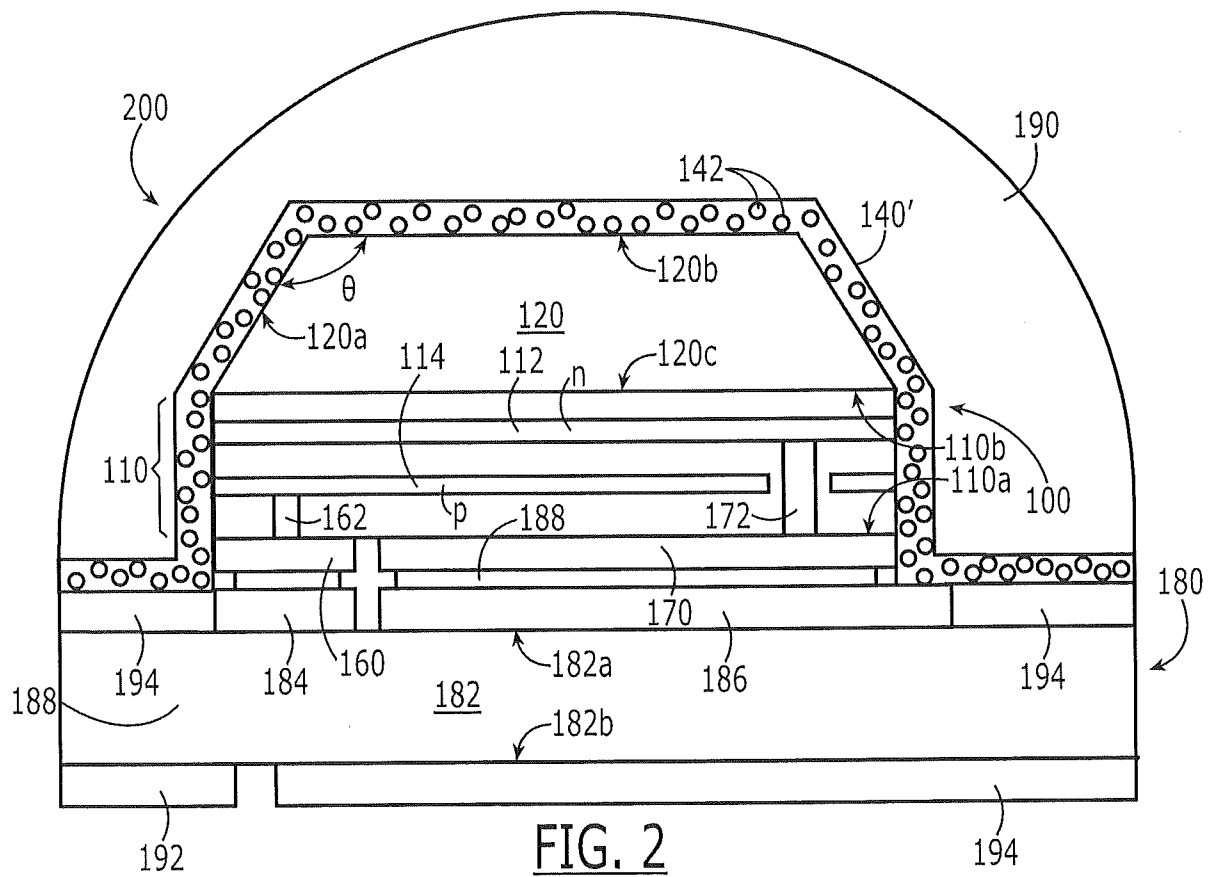
recedes from reflective areas of the substrate beyond the light emitting diode die and also substantially recedes from on an outer face of the light emitting diode die.

71. A method according to Claim 64 wherein the evaporating is followed by applying phosphor directly on the substrate beyond the light emitting diode die and directly on the outer face of the light emitting diode die.

72. A method according to Claim 64 wherein the evaporating is followed by attaching a lens that spans the light emitting diode die and that extends directly on the substrate beyond the light emitting diode die and directly on the outer face of the light emitting diode die.

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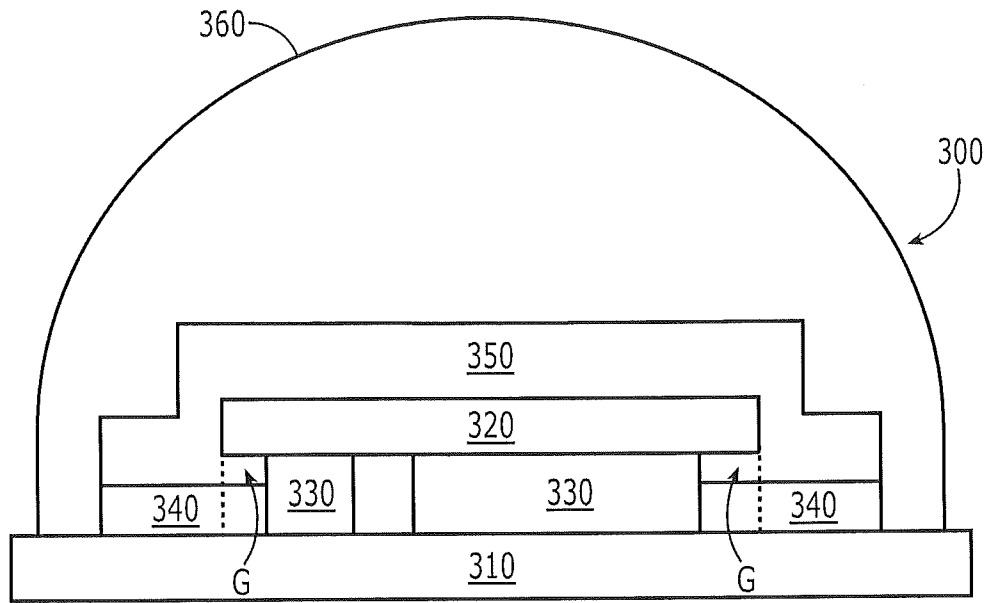


FIG. 3

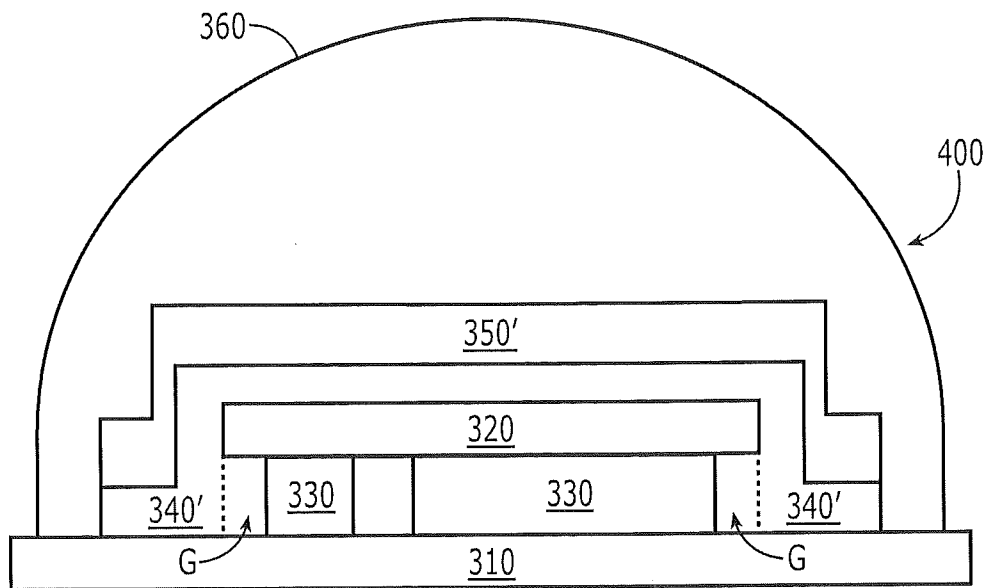


FIG. 4

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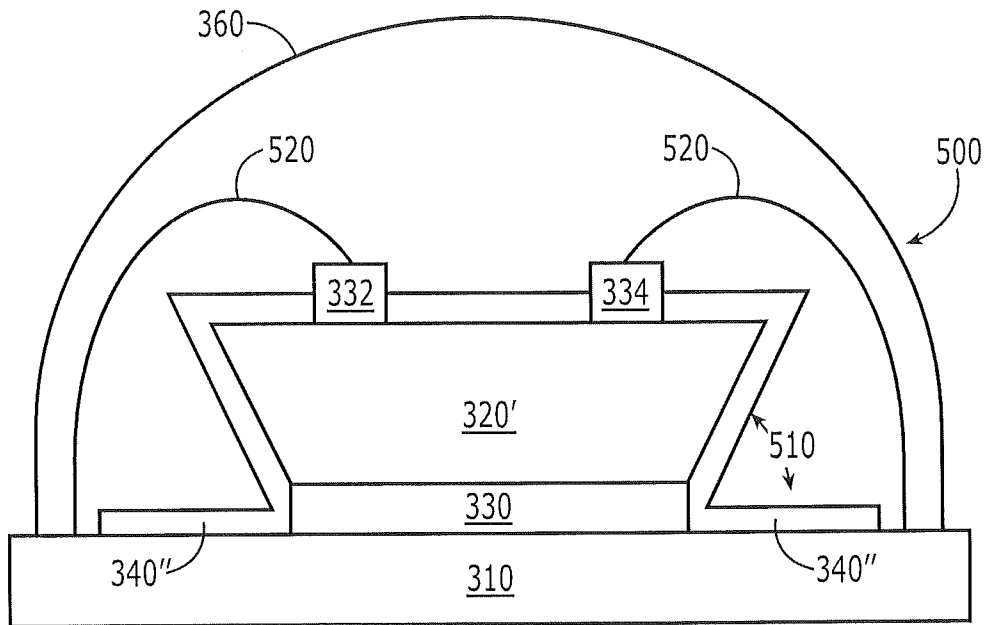


FIG. 5

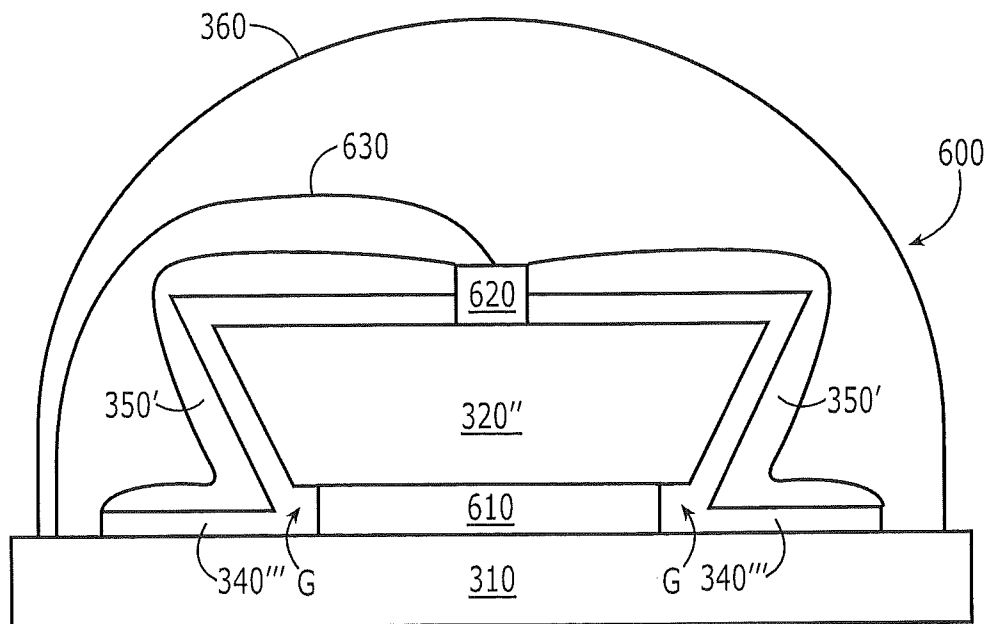
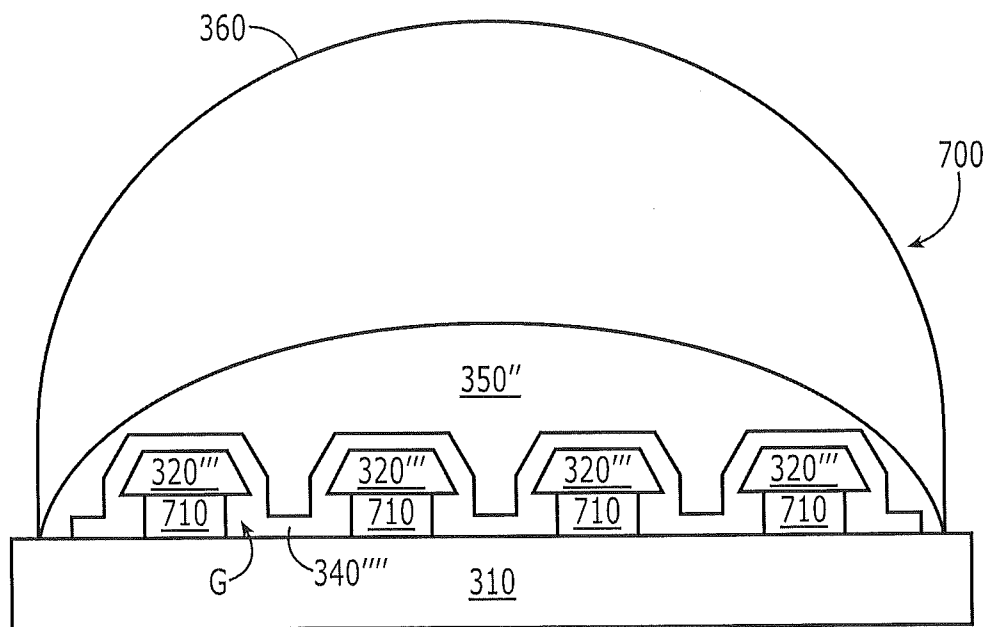
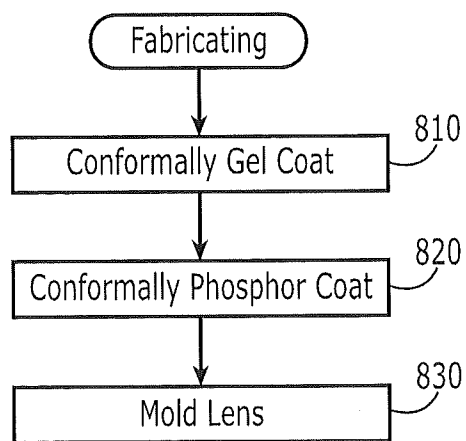


FIG. 6

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FIG. 7FIG. 8

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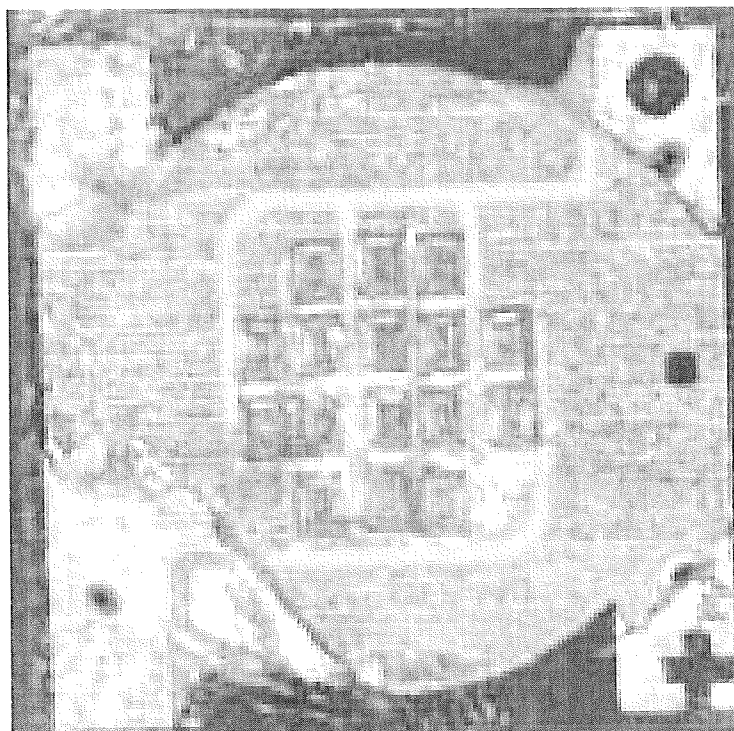


FIG. 9A

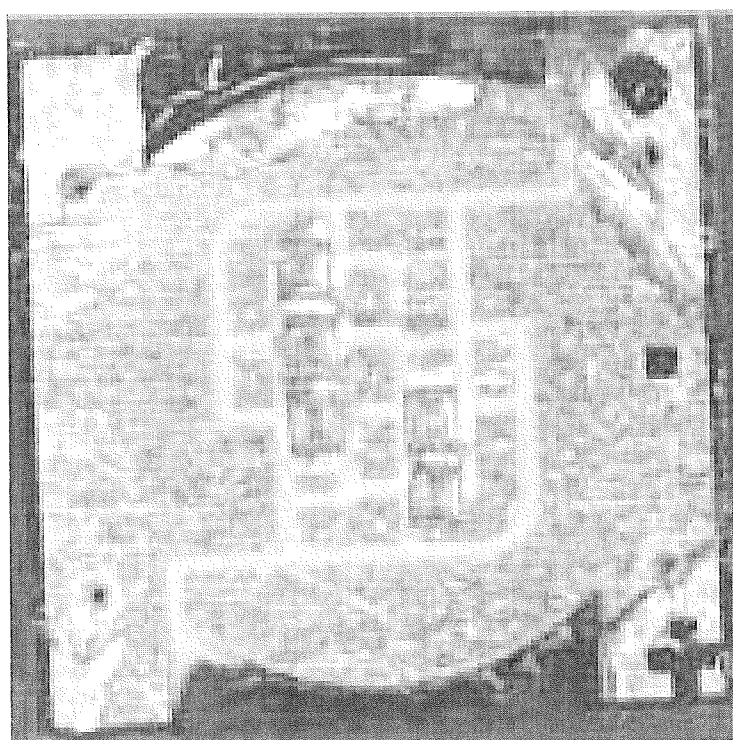


FIG. 9B

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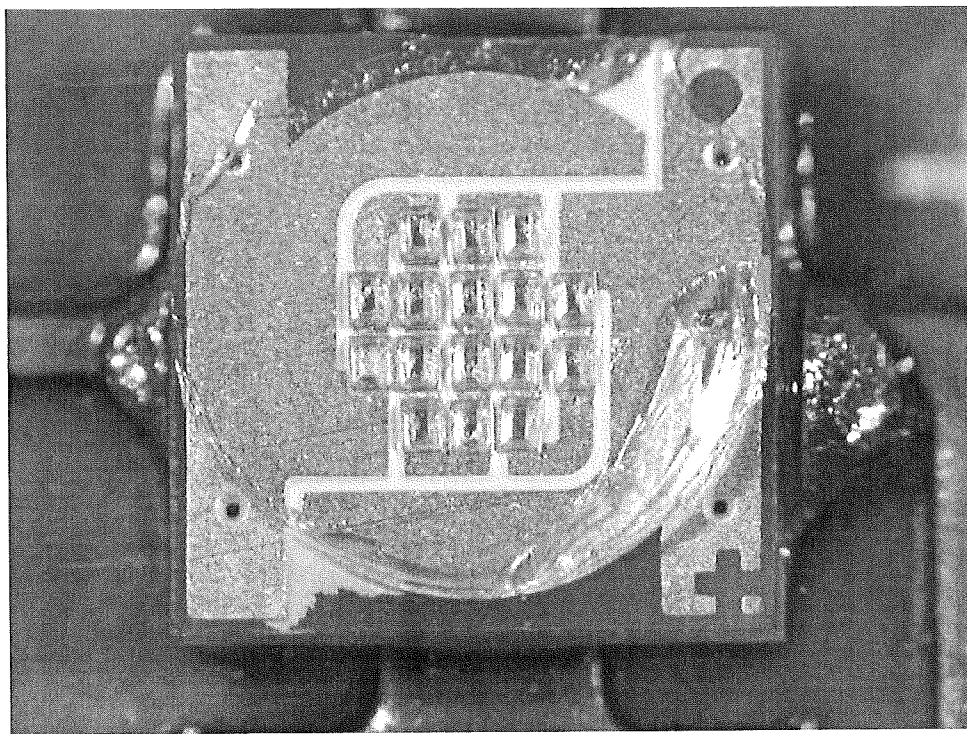


FIG. 9C

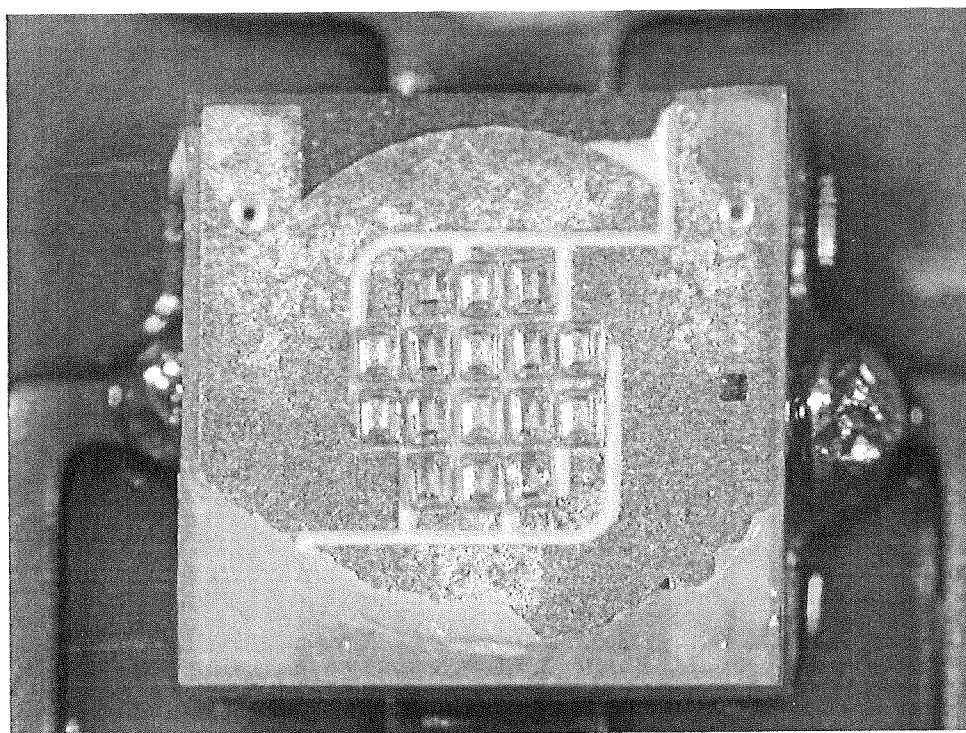
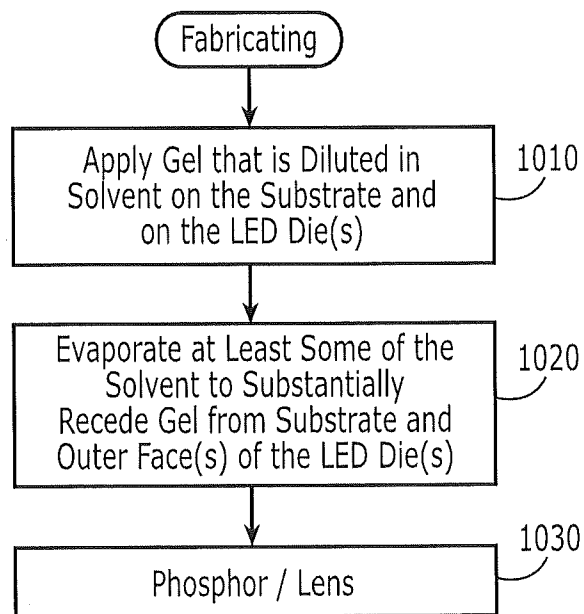
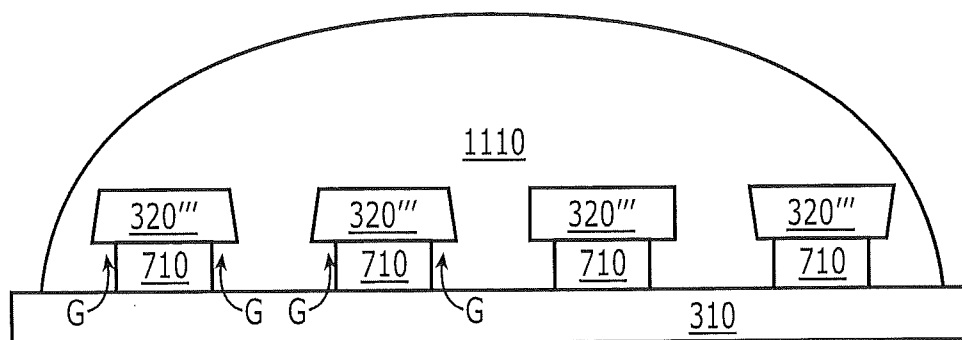
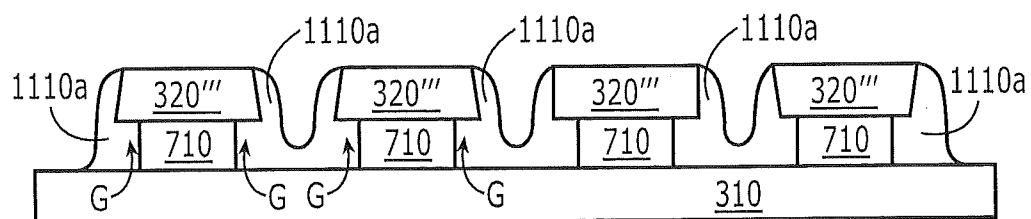


FIG. 9D

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FIG. 10FIG. 11FIG. 12

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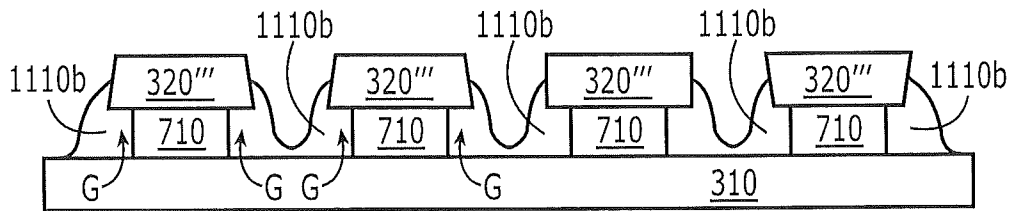


FIG. 13

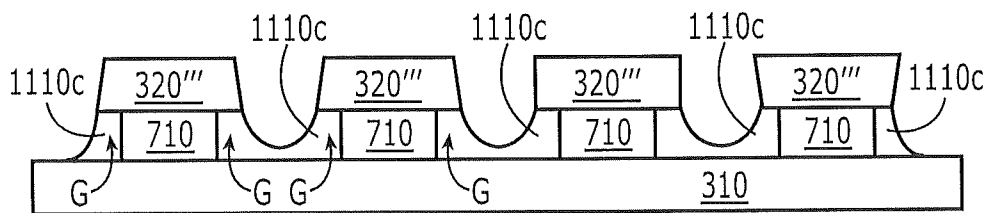


FIG. 14

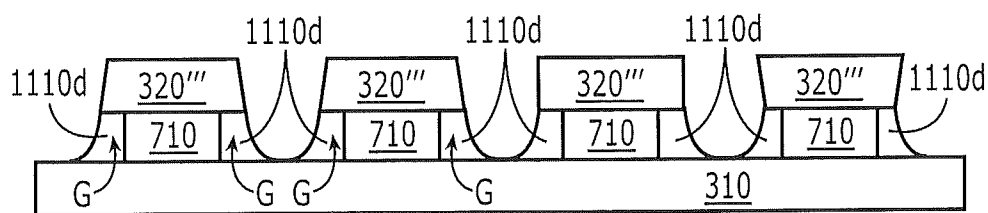


FIG. 15

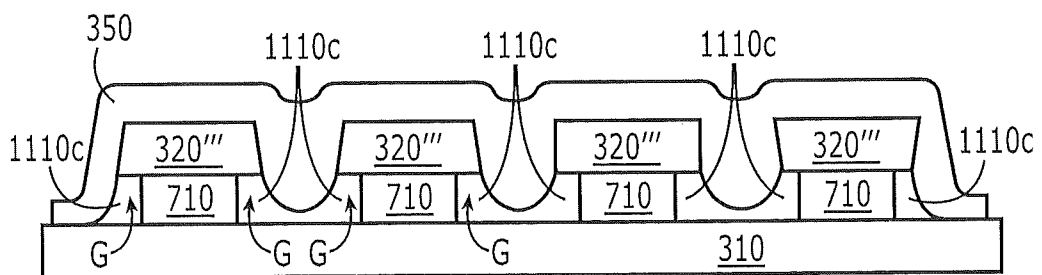


FIG. 16

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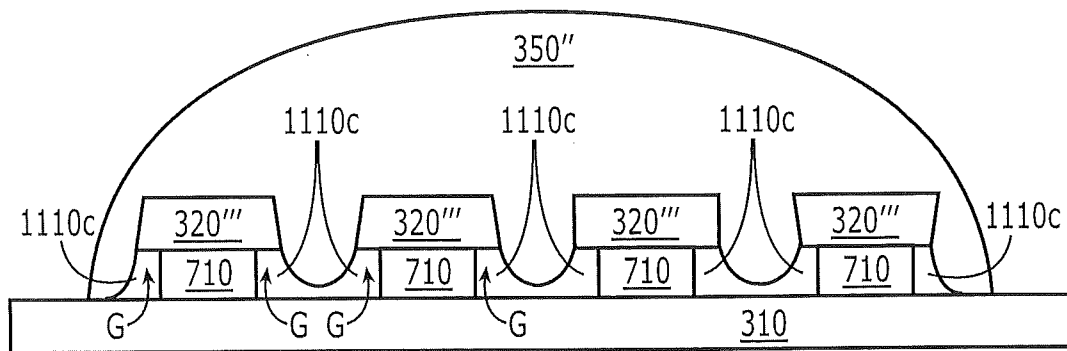


FIG. 17

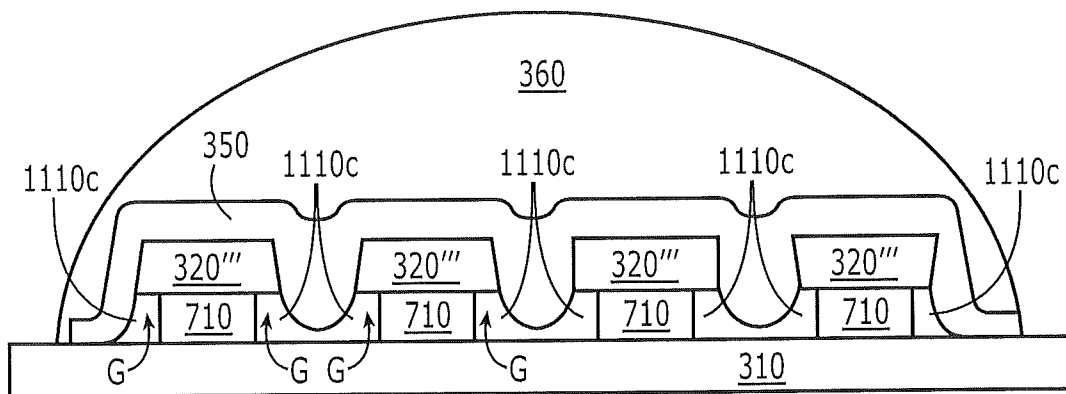


FIG. 18

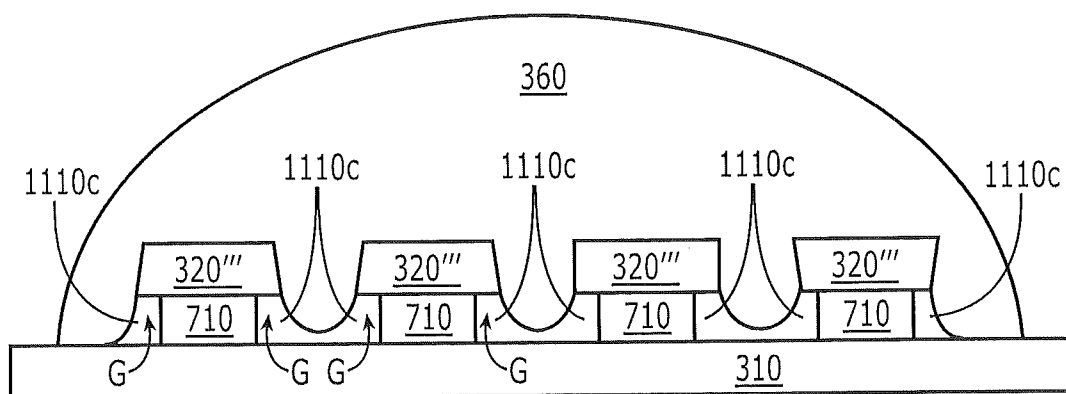


FIG. 19

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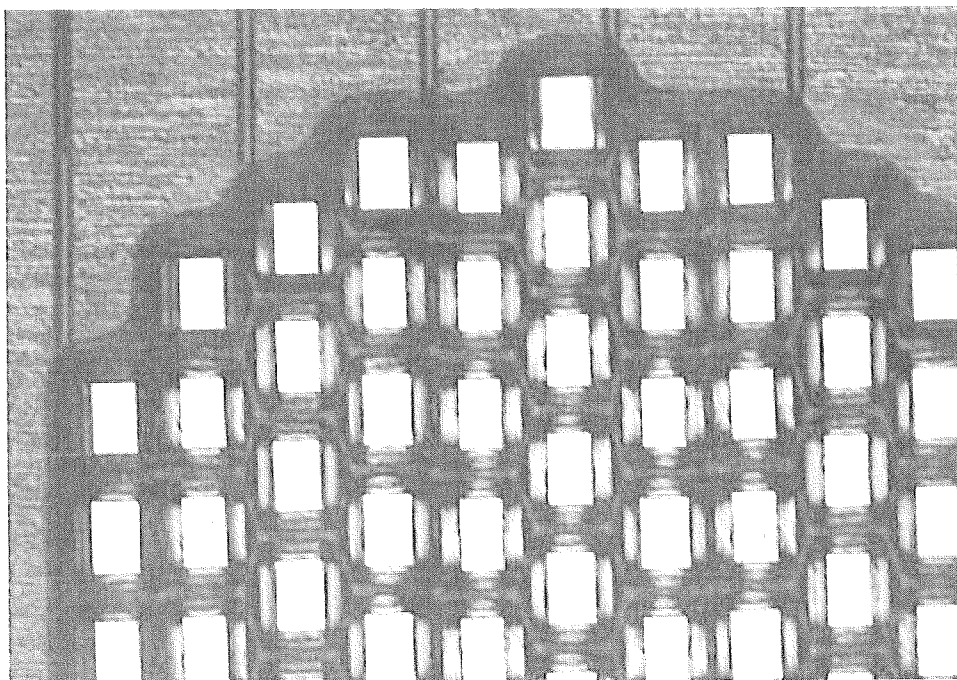


FIG. 20

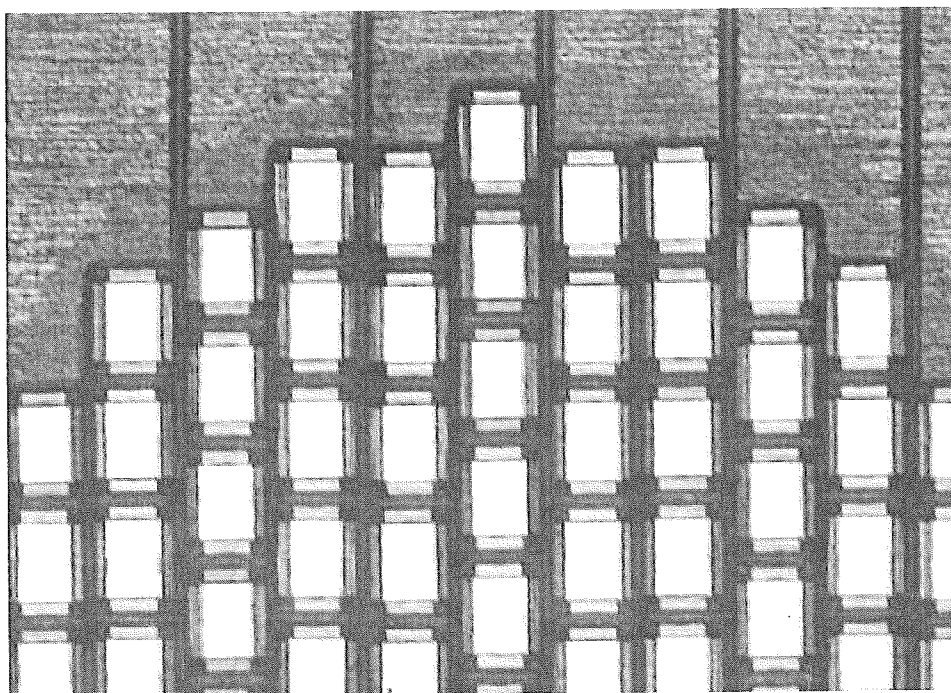


FIG. 21

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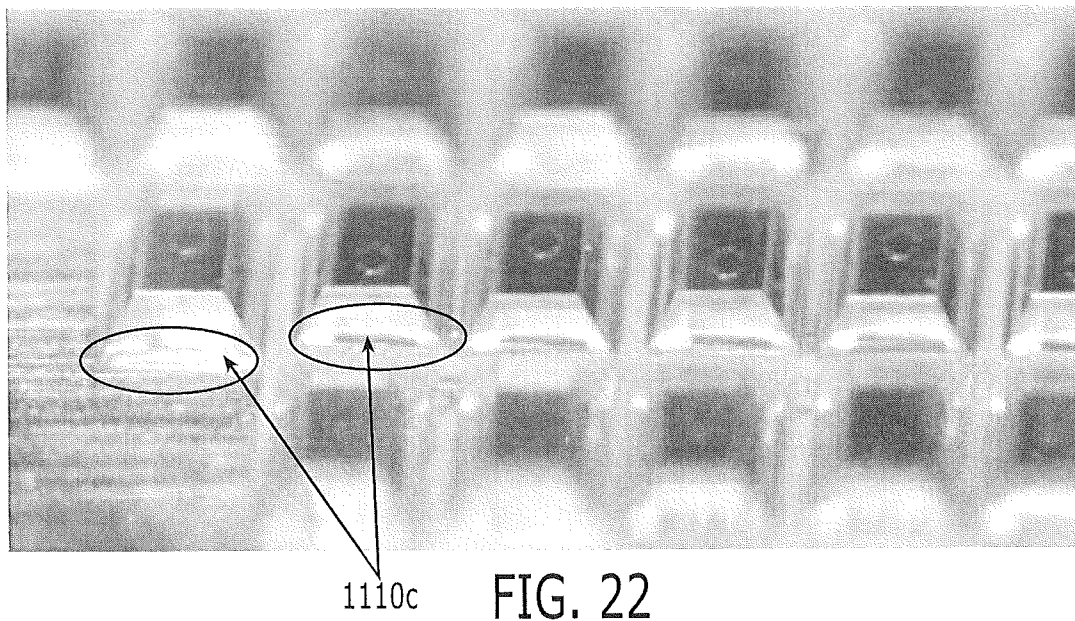


FIG. 22

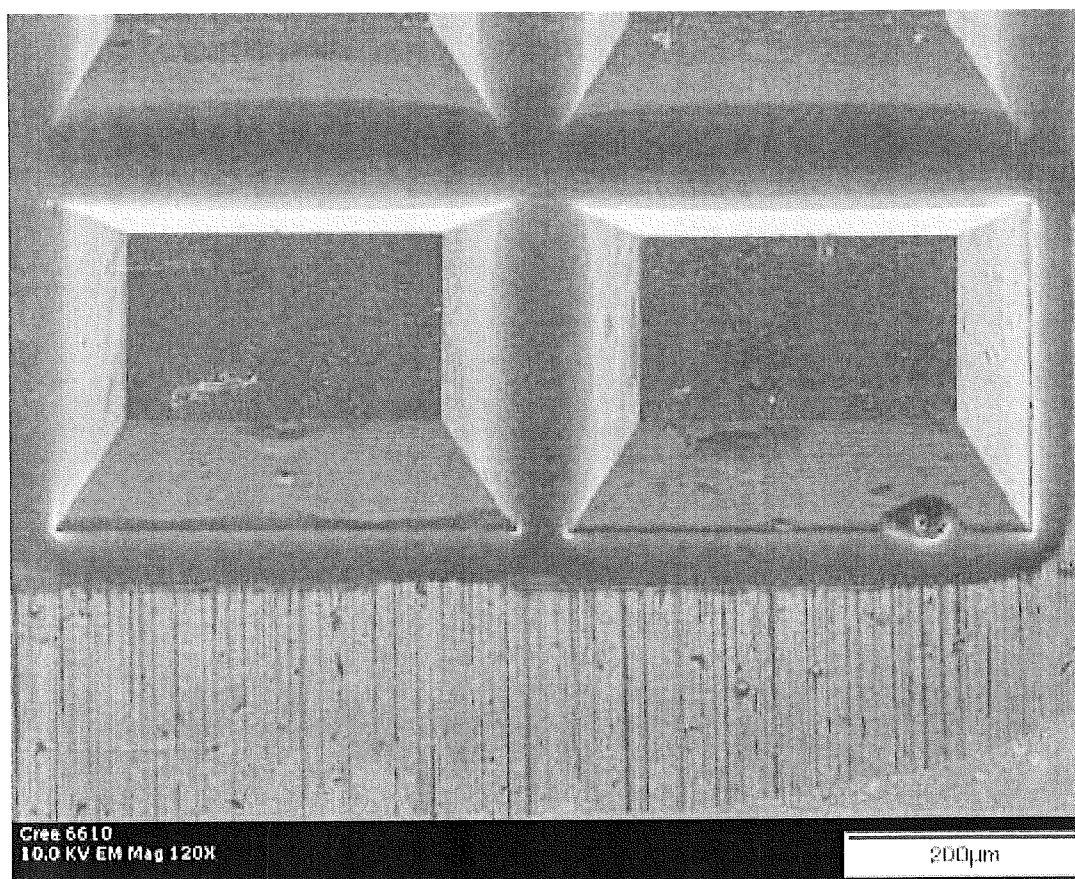


FIG. 23

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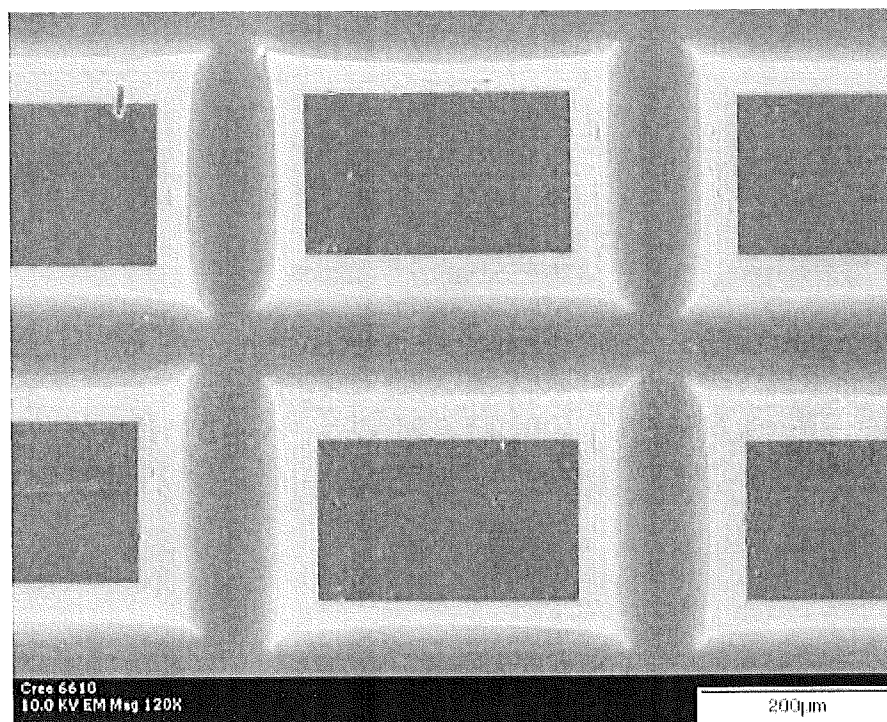


FIG. 24

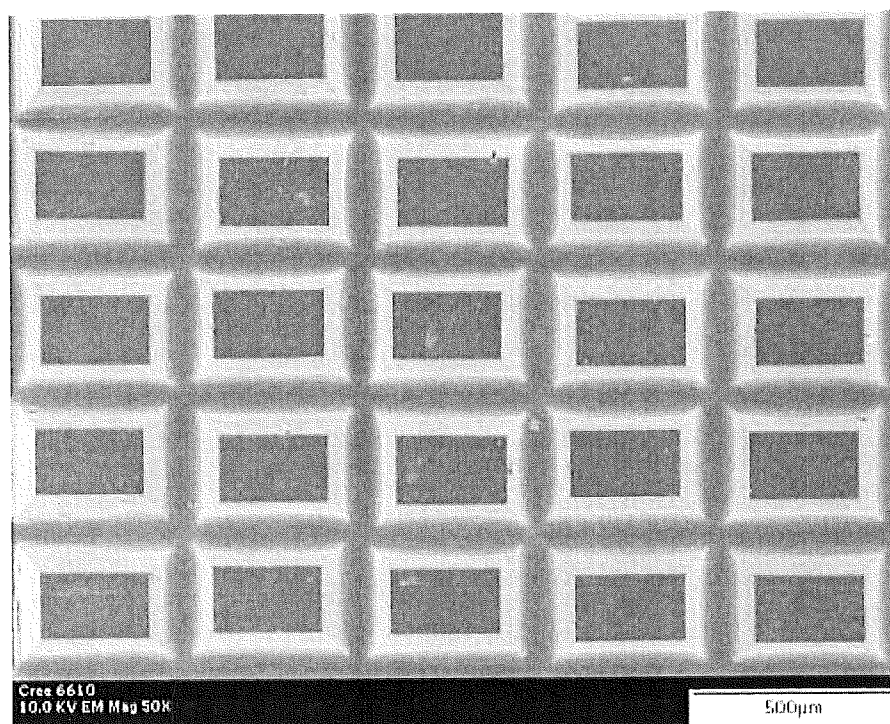
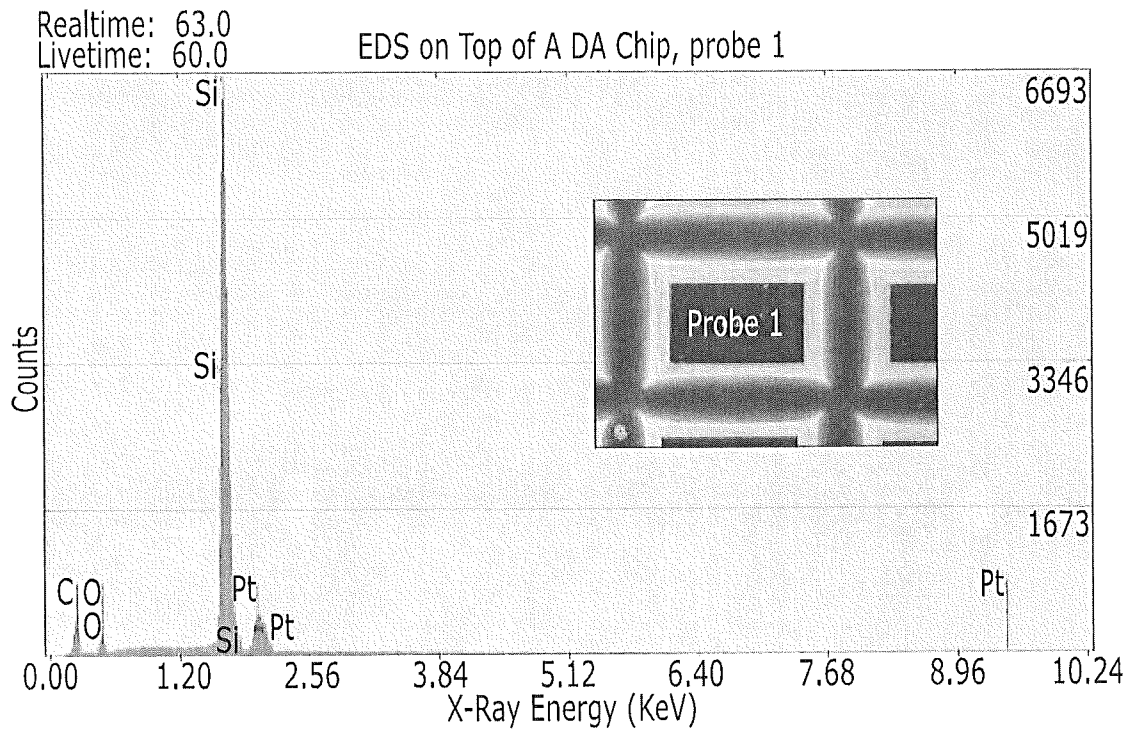


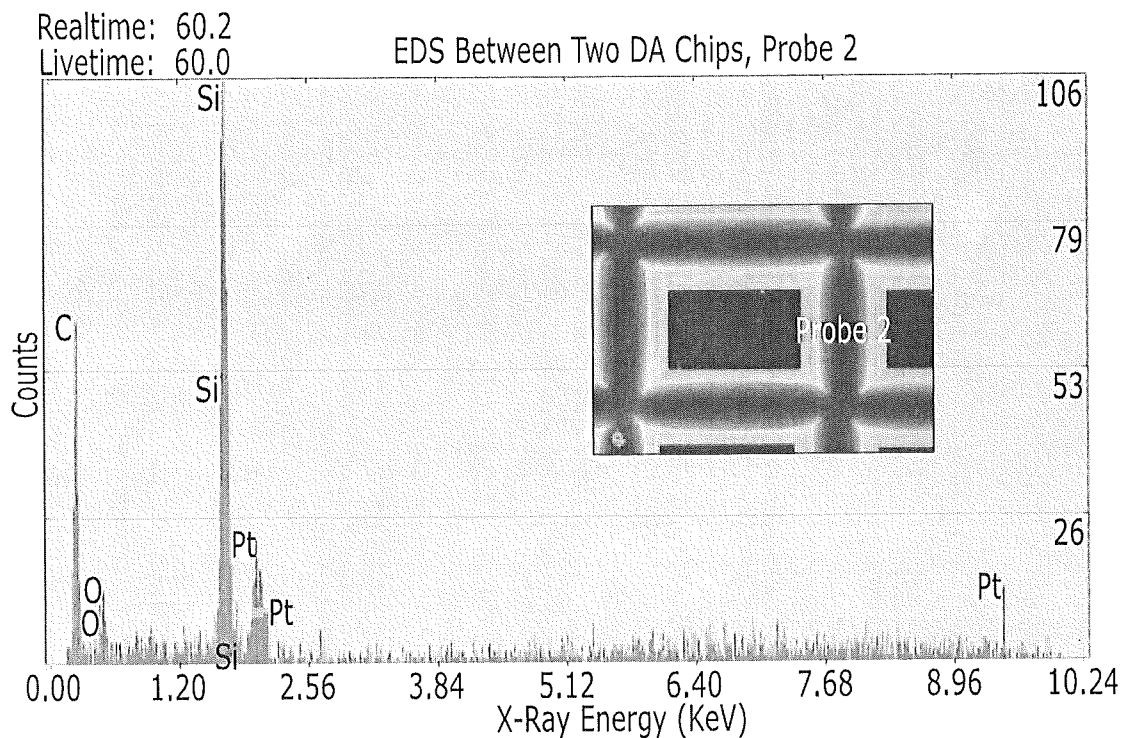
FIG. 25

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Quantitative Results for EDS on Top of A DA Chip, Probe 1
Analysis: Bulk Method: Standardless
Acquired 11-Jan-2012, 10.0 KeV @ 10 + V/channel
No Elements Found

FIG. 26



Quantitative Results for EDS on Top of A DA Chip, Probe 2
Analysis: Bulk Method: Standardless
Acquired 11-Jan-2012, 10.0 KeV @ 10 + V/channel
No Elements Found

FIG. 27

INTERNATIONAL SEARCH REPORT

International application No.

PCT/US 12/41887

A. CLASSIFICATION OF SUBJECT MATTER

IPC(8) - H01L 33/00 (2012.01)

USPC - 257/100

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC(8): H01L 33/00 (2012.01)

USPC: 257/100

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

IPC(8): H01L 33/00 (2012.01);

USPC: 257/79,98-100,787,788 (keyword limited; terms below)

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

PubWEST(USPT,PGPB,EPAB,JPAB); Google Scholar

Search Terms: LED, light, emitting, diode, substrate, die, gel, gap, conformal, array, phosphor, lens, reflector, mirror, contour, region.

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X — Y	US 2011/0121324 A2 (BISBERG) 26 May 2011 (26.05.2011), entire document, especially; FIG 9A-C, 10B, 10 C, 12A, para [0004], [0006], [0051]-[0053], [0055], [0057], [0059], [0061]-[0063], [0066].	1-7, 13, 15, 19, 30, 35-43, 45-49 8-12, 14, 16-18, 31-34, 44, 50-72
X — Y	US 2010/0308354 A1 (DAVID et al.) 09 December 2010 (09.12.2010), entire document, especially; FIG 1-3, 9, 12, para [0001], [0002], [0006], [0007], [0030], [0042], [0044], [0045], [0049], [0051]-[0053].	20-29 8-12, 14, 16-18, 31-34, 44, 50-72
A	US 2005/0233485 A1 (SHISHOV et al.) 20 October 2005 (20.10.2005), entire document.	1-72
A	US 2006/0105483 A1 (LEATHERDALE et al.) 18 May 2006 (18.05.2006), entire document.	1-72

☐ Further documents are listed in the continuation of Box C.

* Special categories of cited documents:

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"E" earlier application or patent but published on or after the international filing date

"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)

"O" document referring to an oral disclosure, use, exhibition or other means

"P" document published prior to the international filing date but later than the priority date claimed

"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

13 August 2012 (13.08.2012)

Date of mailing of the international search report

28 AUG 2012

Name and mailing address of the ISA/US

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